MAX14745

PMIC with Ultra Low I_Q Voltage Regulators and Battery Charger for Small Lithium Ion Systems

General Description

The MAX14745 is a battery-charge-management solution ideal for low-power wearable applications. The device includes a linear battery charger with a smart power selector and several power-optimized peripherals. The MAX14745 features two ultra-low quiescent current buck regulators and three ultra-low quiescent current low-dropout (LDO) linear regulators, providing up to five regulated voltages, each with an ultra-low quiescent current, allows designers to minimize power consumption and extend battery life in 24/7 operation devices, such as those in the wearable market.

The battery charger features a smart power selector that allows operation on a dead battery when connected to a power source. To avoid overloading a power adapter, the input current to the smart power selector is limited based on an I²C register setting. If the charger power source is unable to supply the entire system load, the smart power control circuit supplements the system load with current from the battery. The charger also supports temperature dependent charge currents.

The two synchronous, high-efficiency step-down buck regulators feature a variable frequency mode for increased efficiency during light-load operation. The output voltage of these regulators can be programmed through I²C with the default preconfigured. The buck regulators can support dynamic voltage scaling to further improve system power consumption.

The three configurable LDOs each have a dedicated input pin. Each LDO regulator output voltage can be programmed through I²C with the default preconfigured. The linear regulators can also be configured to operate as power switches that may be used to disconnect the quiescent load of the system peripherals.

The MAX14745 features a programmable power controller that allows the device to be configured for applications that require the device be in a true-off, or always-on, state. The controller also provides a delayed reset signal and voltage sequencing.

The MAX14745 is available in a 36-bump, 0.4mm pitch, 2.72mm x 2.47mm wafer-level package (WLP).

Benefits and Features

- Extend System Use Time Between Battery Charging
 - Dual Ultra-Low-IQ 200mA Buck Regulators
 - Output Programmable from 0.8V to 2.375V and 0.8V to 3.95V
 - 0.9μA (typ) Quiescent Current (Buck 1)
 - Optional Fixed Peak-Current Mode to Optimize Ripple Frequency in Noise-Sensitive Applications
 - Three Ultra-Low-I_O 100mA LDOs
 - LDO1
 - Output Programmable from 0.8V to 3.6V
 - 0.6µA (typ) Quiescent Current
 - 2.7V to 5.5V Input with Dedicated Pin
 - LDO2/3
 - Output Programmable from 0.9V to 4V
 - 1µA (typ) Quiescent Current
 - 1.71V to 5.5V Input with Dedicated Pin
- · Easy-to-Implement Li+ Battery Charging
 - · Smart Power Selector
 - 28V/-5.5V Tolerant Input
 - · Thermistor Monitor
- Minimize Solution Footprint Through High Integration
 - Provides Five Regulated Voltage Rails
 - · Switch Mode Option on Each LDO
- Optimize System Control
 - Monitors Pushbutton for Ultra-Low Power Mode
 - · Power-On Reset Delay and Voltage Sequencing
 - On-Chip Voltage Monitor Multiplexer

Applications

- Wearable Electronics
- Fitness Monitors
- Rechargeable IoT devices

Ordering Information appears at end of data sheet.



TABLE OF CONTENTS

General Description	1
Benefits and Features	1
Applications	1
Typical Application Circuit	5
Absolute Maximum Ratings	6
Package Information	6
Electrical Characteristics	7
Typical Operating Characteristics	22
Bump Configuration	25
Bump Description	25
Block Diagram	27
Detailed Description	27
Power Regulation	27
Power On/Off and Reset Control	27
Power Sequencing	30
Smart Power Selector	31
Thermal Current Regulation	31
System Load Switch	32
Input Limiter	32
Fast-Charge Current Setting	
Thermistor Monitoring with Charger Shutdown	
I ² C Interface	
I ² C Addresses	
Thermistor Monitoring with Charger Shutdown	36
I ² C Interface	38
Start, Stop, And Repeated Start Conditions	
Slave Address	
Bit Transfer	
Single-Byte Write	
Burst Write	39
Single Byte Read	
Burst Read	40
Acknowledge Bits	40
I ² C Register Map	
I ² C Register Descriptions	
Applications Information	62

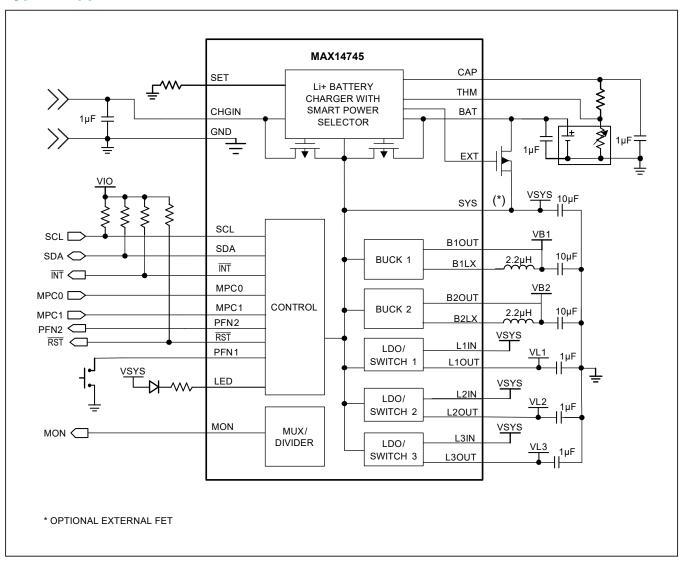
TABLE OF CONTENTS (continued)	
Inductor Selection	62
Output Capacitor Selection	62
Input Capacitor Selection	62
PCB Layout and Routing	62
Ordering Information	66
Inductor Selection. Output Capacitor Selection. Input Capacitor Selection. PCB Layout and Routing Ordering Information Chip Information. Revision History. LIST OF FIGURES Figure 1. Power Function Input Control Modes Flow Diagrams Figure 2a. Power-On Sequencing Figure 2b. Power-On Sequencing Without Battery. Figure 3. Smart Power Selector Current/Voltage Behavior. Figure 4a. Charging Behavior Using Thermistor Monitoring Mode Figure 4b. Charging Behavior Using Thermistor Monitoring with Charger Shutdown). Figure 5b. Battery Charger State Diagram (Thermistor Monitoring with Charger Shutdown). Figure 6b. I2C START, STOP and REPEATED START Conditions Figure 7. Write Byte Sequence Figure 8. Burst Write Sequence Figure 9. Read Byte Sequence Figure 9. Read Byte Sequence Figure 11. Acknowledge. LIST OF TABLES Table 1. Power Function Input Control Modes. Table 2. Thermistor Monitoring/JEITA Monitoring Enable Control. Table 3. I2C Slave Addresses Table 4. Chipld Register (0x00)	66
Revision History	67
LIST OF FIGURES	
Figure 1. Power Function Input Control Modes Flow Diagrams	29
Figure 2b. Power-On Sequencing Without Battery	31
Figure 4a. Charging Behavior Using Thermistor Monitoring Mode	34
Figure 4b. Charging Behavior Using JEITA Monitoring 1 and 2 Modes	34
Figure 5a. Charger State Diagram (Thermistor Monitoring with Charger Shutdown)	36
Figure 5b. Battery Charger State Diagram (JEITA Monitoring with Charger Shutdown)	37
Figure 6. I ² C START, STOP and REPEATED START Conditions	38
Figure 7. Write Byte Sequence	38
Figure 8. Burst Write Sequence	39
Figure 9. Read Byte Sequence	39
Figure 10. Burst Read Sequence	40
Figure 11. Acknowledge	40
LIST OF TABLES	
Table 1. Power Function Input Control Modes	28
Table 2. Thermistor Monitoring/JEITA Monitoring Enable Control	35
Table 3. I ² C Slave Addresses	38
Table 5. ChipRev Register (0x01)	
Table 6. StatusA Register (0x02)	
Table 7. StatusB Register (0x03)	

MAX14745

PMIC with Ultra Low I_Q Voltage Regulators and Battery Charger for Small Lithium Ion Systems

LIST OF TABLES (continued)	
Table 8. StatusC Register (0x04)	
Table 9. IntA Register (0x05)	46
Table 10. IntB Register (0x06)	46
Table 11. IntMaskA Register (0x07)	47
Table 12. IntMaskB Register (0x08)	48
Table 13. ILimCntl Register (0x09)	48
Table 14. ChgCntlA Register (0x0A)	49
Table 15. ChgCntlB Register (0x0B)	50
Table 16. ChTmr Register (0x0C)	51
Table 17. Buck1Cfg Register (0x0D)	51
Table 18. Buck1VSet Register (0x0E)	52
Table 19. Buck2Cfg Register (0x0F)	52
Table 20. Buck2VSet Register (0x10)	53
Table 21. Buck1/2ISet Register (0x11)	53
Table 22. LDO1Cfg Register (0x12)	54
Table 23. LDO1VSet Register (0x13)	54
Table 24. LDO2Cfg Register (0x14)	55
Table 25. LDO2VSet Register (0x15)	55
Table 26. LDO3Cfg Register (0x16)	56
Table 27. LDO3VSet Register (0x17)	56
Table 28. ThrmCfg Register (0x18)	57
Table 29. ThrmCfg Register (0x19)	58
Table 30. MONCfg Register (0x1A)	58
Table 31. BootCfg Register (0x1B)	59
Table 32. PinStat Register (0x1C)	59
Table 33. Buck1/2Extra Control Register (0x1D)	60
Table 34. PwrCfg Register (0x1E)	61
Table 35. PwrCmd Register (0x1F)	61
Table 36. Suggested Inductors	62
Table 37. Output Capacitor Values*	62
Table 38. Register Bit Default Values	63
Table 39. Register Default Values	65

Typical Application Circuit



MAX14745

PMIC with Ultra Low I_Q Voltage Regulators and Battery Charger for Small Lithium Ion Systems

Absolute Maximum Ratings

(Voltages	referenced to GND.)	
SDA, SCL	, THM, RST, SYS, PFN1, PF	FN2,
MPC0, I	MPC1, ĪNT, MON, BAT, LED	,
L1IN, L2	2IN, L3IN	0.3V to +6.0V
	X, B1OUT, B2OUT, EXT	
L10UT		$-0.3V$ to $(V_{L1IN} + 0.3V)$
L20UT		$-0.3V$ to $(V_{L2IN} + 0.3V)$
L3OUT		$\cdot -0.3V \text{ to } (V_{L3IN} + 0.3V)$
CHGIN		6V to +30V
CAP	0.3V to mi	n (V _{CHGIN} + 0.3V, +6V)
SET		0.3V to V _{BAT} + 0.3V

Continuous Current into CHGIN, BAT, SYS	±1000mA
Continuous Current into any other terminal	±100mA
Continuous Power Dissipation (multilayer be	oard at +70°C):
6 x 6 Array 36-Bump 2.72mm x 2.47mm	
0.4mm Pitch WLP (derate 21.70mW/°C).	1.74W
Operating Temperature Range	40°C to +85°C
Junction Temperature	+150°C
Storage Temperature Range	
Soldering Temperature (reflow)	+260°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Package Information

PACKAGE TYPE: 36 WLP				
Package Code	W362D2+1			
Outline Number	21-0897			
Land Pattern Number	Refer to Application Note 1891			
THERMAL RESISTANCE, FOUR-LAYER BOARD				
Junction to Ambient (θ _{JA})	46°C/W			

For the latest package outline information and land patterns (footprints), go to www.maximintegrated.com/packages. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to www.maximintegrated.com/thermal-tutorial.

Electrical Characteristics

 $(V_{CHGIN} = 5.0V, V_{BAT} = 3.7V, T_A = -40^{\circ}C$ to +85°C, all registers in their default state, unless otherwise noted. Typical values are at $T_A = +25^{\circ}C$.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
GLOBAL SUPPLY CURR	ENT (L_IN Connected	t to SYS)				
		All functions disabled		0.26		
Charger Input Current	^I снg	Power on, V _{CHGIN} = 5V SYS switch closed, buck regulators enabled, LDO1 enabled, I _{SYS} = 0A, I _{B_OUT} = 0A, I _{L_OUT} = 0A			1.5	mA
		Power off, V _{CHGIN} = 0V, SYS switch open		0.96	1.7	
		Power on, V _{CHGIN} = 0V SYS switch closed, 2x buck regulators enabled, LDOs disabled. I _{SYS} = 0A, I _{B_OUT} = 0A		2.8	4.3	
BAT Input Current	^I ВАТ	Power on, V _{CHGIN} = 0V SYS switch closed, 2x buck regulators enabled, LDO1 enabled, I _{SYS} = 0A, I _{B_OUT} = 0A, I _{L_OUT} = 0A		3.5	7	μА
		Power on, V _{CHGIN} = 0V SYS switch closed, 2x buck regulators enabled, 3x LDOs enabled, I _{SYS} = 0A, I _{B_OUT} = 0A, I _{L_OUT} = 0A		5.2		
BUCK REGULATOR 1 (V _{SYS} = +3.7V, L = 2.2µH,	. C = 2.2µF, V _{B1OUT} =	1.2V)				
Input Voltage	V _{IN BUCK1}	Input voltage = V _{SYS}	2.7		5.5	V
Output Voltage	Vout BUCK1	25mV step resolution	0.8		2.375	V
Output UVLO Voltage	Vuvlo_buck1	Note: For V _{OUT} < UVLO ZC is imposed		0.44	0.7	V
Quiescent Supply Current	IQ_BUCK1	Buck enabled, $I_{B1OUT} = 0mA$, $V_{SYS} = 3.7V$, $V_{B1OUT} = 1.2V$ (Note 2)		0.9	1.3	μΑ
Dropout Quiescent Supply Current	IQDO_BUCK1	I _{B1OUT} = 0mA, (V _{SYS} – V _{OUT}) ≤ 0.1V		1.1		mA
Shutdown Supply Current with Active Discharge Enabled	I _{SD_BUCK1}	Buck1 disabled, Buck1ActDSC=1.		60		μА
Output Accuracy	ACC _{BUCK1}	I _{B1OUT} = 1mA	-3		+3.1	%
Peak-to-Peak Ripple	VPPRIPPLE1	Buck1lSet = 100mA, C _{OUT} = 2.2μF, I _{B1OUT} = 1mA		10		mV
I _{PEAK} Set Range	I _{PEAK_BUCK1}	25mA step resolution set by Buck1lSet[3:0].	50		375	mA

Electrical Characteristics (continued)

 $(V_{CHGIN} = 5.0V, V_{BAT} = 3.7V, T_A = -40^{\circ}C$ to +85°C, all registers in their default state, unless otherwise noted. Typical values are at $T_A = +25^{\circ}C$.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Load Regulation Error	V _{LOADR_BUCK1}	Buck1ISet = 150mA, Buck1IAdptEnb = 0, I _{B1OUT} = 300mA		-3		%
Line Regulation Error	V _{LINER_BUCK1}	V _{B1OUT} = 1.2V; V _{SYS} from 2.7V to 5.5V		3		mV
Maximum Operating Output Current	lout_Buck1	V _{SYS} = 3.7V, Buck1VSet = 1.2V, Buck1ISet = 200mA, Buck1IAdptEnb = 0, load regulation error = -5%	200	500		mA
B1OUT Pulldown Current	ILEAK_B1OUT	Buck1 enabled		110		nA
B1OUT Pulldown Resistance	R _{PD_B1OUT}	Buck1 disabled, V _{B1OUT} = 1.2V		12		ΜΩ
M00 0 D 11	5	Buck1FFET = 0		0.27	0.5	Ω
pMOS On-Resistance	R _{ONP_BUCK1}	Buck1FFET = 1		0.55	1	Ω
-MOC O- Di-t	D	Buck1FFET = 0		0.24	0.45	Ω
nMOS On-Resistance	R _{ONN_BUCK1}	Buck1FFET = 1		0.43	0.9	Ω
Freewheeling On-Resistance	R _{ONFW_BUCK1}	V _{SYS} = 3.7V, V _{B1OUT} = 1.2V		7.3	13	Ω
Minimum T _{ON}	T _{ON MIN}			40	80	ns
Maximum Duty Cycle	D _{MAX} BUCK1	Buck1IAdptEnb = 0		98		%
Switching Frequency	fsw_Buck1	Load regulation error = -3%		3		MHz
Average Current During Short-Circuit to GND	I _{SHRT_BUCK1}	Buck1ISet = 150mA, Buck1IAdptEnb = 0, V _{B1OUT} = 0V		100		mA
BLX Leakage Current	I _{BLX_BUCK1}			0.005	1	μA
Active Discharge Current	I _{PD_BUCK1}	V _{B1OUT} = 1.2V		17		mA
Passive Discharge Resistance	R _{PD_BUCK1}	V _{B1OUT} = 1.2V		9		kΩ
Full Turn-On Time	^t ON_BUCK1	Time from enable to full current capability, Buck1Fst = 0		58		ms
Efficiency	Eff _{BUCK1}	I _{LOAD} = 10mA, Buck1ISet = 150mA, Inductor = BOURNS SRP2010- 2R2M, V _{B1OUT} = 1.2V		87		%
BLX Rising/Falling Slew	CD	Buck1LowEMI = 0		2		1//22
Rate	SR _{BLX_BUCK1}	Buck1LowEMI = 1		0.5		V/ns
Thermal-Shutdown Temperature	T _{SHDN_BUCK1}			140		°C
Thermal-Shutdown Temperature Hysteresis	TSHDN_HYST_BUCK1			10		°C

Electrical Characteristics (continued)

 $(V_{CHGIN} = 5.0V, V_{BAT} = 3.7V, T_A = -40^{\circ}C$ to +85°C, all registers in their default state, unless otherwise noted. Typical values are at $T_A = +25^{\circ}C$.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
BUCK REGULATOR 2						
$(V_{SYS} = +3.7V, L = 2.2\mu H)$						
Input Voltage	V _{IN_BUCK2}	Input voltage = V _{SYS}	2.7		5.5	V
Output Voltage	V _{OUT_BUCK2}	50mV step resolution	0.8		3.95	V
Output UVLO Voltage	V _{UVLO_BUCK2}	Note: For V _{OUT} < UVLO ZC is imposed		0.44	0.7	V
Quiescent Supply Current	IQ_BUCK2	Buck enabled, I _{B2OUT} = 0mA, V _{SYS} = 3.7V, V _{B2OUT} = 1.2V (Note 2)		1	1.3	μА
Dropout Quiescent Supply Current	IQDO_BUCK2	I _{B2OUT} = 0mA, V _{SYS} – V _{B2OUT} ≤ 0.1V		1.1		mA
Shutdown Supply Current with Active Discharge Enabled	I _{SD_BUCK2}	Buck1 disabled, Buck2ActDSC = 1.		60		μА
Output Accuracy	ACC _{BUCK2}	I _{B2OUT} = 1mA, V _{B2OUT} < 3.4V	-3		+3.1	%
Peak-to-Peak Ripple	V _{PPRIPPLE2}	Buck2lSet = 100mA, C _{OUT} = 2.2μF, I _{B2OUT} = 1mA		10		mV
I _{PEAK} Set Range	I _{PEAK_BUCK2}	25mA step resolution set by Buck2ISet[3:0].	50		375	mA
Load Regulation Error	VLOADR_BUCK2	Buck2ISet = 150mA, Buck2IAdptEnb = 0, I _{B2OUT} = 300mA		-3		%
Line Regulation Error	V _{LINER_BUCK2}	V _{B2OUT} = 1.2V; V _{SYS} from 2.7V to 5.5V		3		mV
Maximum Operating Output Current	lout_buck2	V _{SYS} = 3.7V, Buck2VSet = 1.2V, Buck2ISet = 200mA, Buck2IAdptEnb = 0, load regulation = -5%	200	500		mA
B2OUT Pulldown Current	I _{LEAK_B2OUT}	Buck2 enabled		220		nA
B2OUT Pulldown Resistance	R _{PD_B2OUT}	Buck2 disabled, V _{B2OUT} = 1.2V		6		ΜΩ
nMOS On Besistanes	В	Buck2FFET = 0		0.27	0.5	Ω
pMOS On-Resistance	R _{ONP_BUCK2}	Buck2FFET = 1		0.55	1	Ω
-MOC O- D	Б	Buck2FFET = 0		0.24	0.45	Ω
nMOS On-Resistance	R _{ONN_BUCK2}	Buck2FFET = 1		0.43	0.9	Ω
Freewheeling On-Resistance	R _{ONFW_BUCK2}	V _{SYS} = 3.7V, V _{B2OUT} = 1.2V		7.3	13	Ω

Electrical Characteristics (continued)

 $(V_{CHGIN} = 5.0V, V_{BAT} = 3.7V, T_A = -40^{\circ}C$ to +85°C, all registers in their default state, unless otherwise noted. Typical values are at $T_A = +25^{\circ}C$.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Minimum T _{ON}	T _{ON_MIN}			40	80	ns
Maximum Duty Cycle	D _{MAX_BUCK2}	Buck2IAdptEnb = 0		98		%
Switching Frequency	fsw_Buck2	Load regulation error = -3%		3		MHz
Average Current During Short-Circuit to GND	I _{SHRT_BUCK2}	Buck2ISet = 150mA, Buck2IAdptEnb = 0, V _{B2OUT} = 0V		100		mA
BLX Leakage Current	I _{BLX_BUCK2}			0.005	1	μA
Active Discharge Current	I _{PD_BUCK2}	V _{B2OUT} = 1.2V		17		mA
Passive Discharge Resistance	R _{PD_BUCK2}	V _{B2OUT} = 1.2V		9		kΩ
Full Turn-On Time	T _{ON_BUCK2}	Time from enable to full current capability, Buck2Fst = 0		58		ms
Efficiency	Eff _{BUCK2}	I _{LOAD} = 10mA, Buck2ISet = 150mA, Inductor = BOURNS SRP2010- 2R2M, V _{B2OUT} = 1.2V		87		%
BLX Rising/Falling Slew	CD.	Buck2LowEMI = 0		2) //
Rate	SR _{BLX_BUCK2}	Buck2LowEMI = 1		0.5		V/ns
Thermal-Shutdown Temperature	T _{SHDN_BUCK2}			140		°C
Thermal-Shutdown Temperature Hysteresis	T _{SHDN_HYST_BUCK2}			10		°C
LDO1 (C = 1µF, unless otherwis	e noted. Typical values	are at $V_{L1IN} = 3.7V$, with $I_{L1OUT} = 10m$	4, V _{L1OUT} =	= 3V.)		
Input Voltage	V	LDO mode	2.7		5.5	V
Input voltage	V _{INLDO1}	Switch mode	1.2		5.5	V
Quiescent Supply		LDO enabled, I _{L1OUT} = 0µA		0.55	4	
Current	I _{Q_LDO1}	LDO enabled, I _{L1OUT} = 0μA, Switch mode		0.45		μA
Shutdown Supply Current with Active Discharge Enabled	I _{SD_LDO1}	LDO1 disabled. LDO1ActDSC=1.		55		μА
Maximum Output Current	I _{L1OUT_MAX}		100			mA
Output Voltage	V _{L1OUT}		0.8		3.6	V
Output Accuracy	ACC _{LDO1}	$V_{L1IN} = (V_{L1OUT} + 0.5V)$ or higher, $I_{L1OUT} = 100\mu A$	-2.7		+2.7	%

Electrical Characteristics (continued)

 $(V_{CHGIN} = 5.0V, V_{BAT} = 3.7V, T_A = -40^{\circ}C$ to +85°C, all registers in their default state, unless otherwise noted. Typical values are at $T_A = +25^{\circ}C$.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Dropout Voltage	V _{DROP_LDO1}	V _{L1IN} = 3V, I _{L1OUT} = 100mA, LDO1VSet = 3V			102	mV
Line Regulation Error	V _{LINEREG_LDO1}	$V_{L1IN} = (V_{L1OUT} + 0.5V)$ to 5.5V	-0.12	0.022	+0.12	%/V
Load Regulation Error	VLOADREG_LDO1	I _{L1OUT} = 100μA to 100mA		0.002	0.005	%/mA
Line Transient	V	V _{L1IN} = 4V to 5V, 200ns rise time		±36		mV
Line Hansient	V _{LINETRAN_LDO1}	V _{L1IN} = 4V to 5V, 1µs rise time		±28		mV
	V	I _{L1OUT} = 0mA to 10mA, 200ns rise time		145		mV
Load Transient	VLOADTRAN_LDO1	I _{L1OUT} = 0mA to 100mA, 200ns rise time		290		mV
Passive Discharge Resistance	R _{PD_LDO1}		5	10	16	ΚΩ
Active Discharge Current	I _{ADL_LDO1}	V _{L1IN} = 3.7V	7	20	37	mA
Switch Mode Resistance		V _{L1IN} = 2.7V, I _{L1OUT} = 100mA		0.5	0.85	
	R _{ON_LDO1}	V _{L1IN} = 1.8V, I _{L1OUT} = 100mA		0.76	1.3	Ω
		V _{L1IN} = 1.2V, I _{L1OUT} = 5mA		1.7	2.8	
Turn-On Time	^t ON_LDO1	I _{L1OUT} = 0mA, time from 10% to 90% of final value		1.6	3.7	ma
Turn-On Time		I _{L1OUT} = 0mA, time from 10% to 90% of final value, Switch mode		0.25	0.65	ms
Chart Circuit Current		V _{L1IN} = 2.7V, V _{L1OUT} = GND	150	345	550	mA
Short-Circuit Current Limit	ISHRT_LD01	V _{L1IN} = 2.7V , V _{L1OUT} = GND, Switch mode	150	335	550	mA
Thermal-Shutdown Temperature	T _{SHDN_LDO1}			150		°C
Thermal-Shutdown Temperature Hysteresis	T _{SHDN_HYST_LDO1}			16		°C
	OUT _{NOISE}	10Hz to 100kHz, V _{L1IN} = 5V, V _{L1OUT} = 3.3V		110		
Output Noise		10Hz to 100kHz, V _{L1IN} = 5V, V _{L1OUT} = 2.5V		95		u\/rma
		10Hz to 100kHz, V _{L1IN} = 5V, V _{L1OUT} = 1.2V		60		- μVrms
		10Hz to 100kHz, V _{L1IN} = 5V, V _{L1OUT} = 0.8V		60		

Electrical Characteristics (continued)

 $(V_{CHGIN} = 5.0V, V_{BAT} = 3.7V, T_A = -40^{\circ}C$ to +85°C, all registers in their default state, unless otherwise noted. Typical values are at $T_A = +25^{\circ}C$.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
LDO2						
(C = 1μF, unless otherwise	noted. Typical values	are at V_{L2IN} = 3.7V, with I_{L2OUT} = 10m/	4, V _{L2OUT} =	= 3V.)		
Input Voltage	V _{INLDO2}	LDO mode	1.71		5.5	V
iliput voltage	VINLDO2	Switch mode	1.2		5.5	V
Quiescent Supply	la	I _{L2OUT} = 0μA		1	5.1	μA
Current	I _{Q_LDO2}	I _{L2OUT} = 0μA, Switch mode		0.5		μΑ
Quiescent Supply Current in Dropout	I _{QDO_LDO2}	$I_{L2OUT} = 0\mu A$, $V_{L2IN} = 2.9V$, LDO2VSet = 3V.		1.8		μА
Shutdown Supply Current with Active Discharge Enabled	I _{SD_LDO2}	LDO2 disabled. LDO2ActDSC=1.		54		μА
Maximum Output		V _{L2IN} ≥ 2.7V	100			mA
Current	I _{L2} OUT_MAX	V _{L2IN} = 1.8V or lower	50			mA
Output Voltage	V _{L2OUT}		0.9		4	V
Output Accuracy	ACC _{LDO2}	V_{L2IN} = (V_{L2OUT} + 0.5V) or higher, I_{L2OUT} = 100 μ A	-2.7		+2.7	%
Dropout Voltage	V _{DROP_LDO2}	V _{L2IN} = 3V, I _{L2OUT} = 100mA, LDO2VSet = 3V			100	mV
Line Regulation Error	V _{LINEREG LDO2}	$V_{L2IN} = (V_{L2OUT} + 0.5V)$ to 5.5V	-0.4	+0.05	+0.4	%/V
Load Regulation Error	V _{LOADREG} LDO2	I _{L2OUT} = 100μA to 100mA		0.001	0.005	%/mA
Line Transient	_	V _{L2IN} = 4V to 5V, 200ns rise time		±35		mV
Line Transient	V _{LINETRAN_LDO2}	V _{L2IN} = 4V to 5V, 1µs rise time		±25		mV
	.,	I _{L2OUT} = 0mA to 10mA, 200ns rise time		100		mV
Load Transient	VLOADTRAN_LDO2	I _{L2OUT} = 0mA to 100mA, 200ns rise time		200		mV
Passive Discharge Resistance	R _{PD_LDO2}		5	10	16	ΚΩ
Active Discharge Current	I _{ADL_LDO2}	V _{L2IN} = 3.7V	7	20	37	mA
		V _{L2IN} = 2.7V, I _{L2OUT} = 100mA		0.46	0.76	
Switch Mode Resistance	R_{ON_LDO2}	V _{L2IN} = 1.8V, I _{L2OUT} = 50mA		0.7	1.15	Ω
Nooistanoo	- -	V _{L2IN} = 1.2V, I _{L2OUT} = 5mA		1.7	2.6	
Turn On Time	.	I _{L2OUT} = 0mA, time from 10% to 90% of final value		1.5	3.7	no o
Turn-On Time	t _{ON_LDO2}	I _{L2OUT} = 0mA, time from 10% to 90% of final value, Switch mode		0.25	0.65	ms

Electrical Characteristics (continued)

 $(V_{CHGIN} = 5.0V, V_{BAT} = 3.7V, T_A = -40^{\circ}C$ to +85°C, all registers in their default state, unless otherwise noted. Typical values are at $T_A = +25^{\circ}C$.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Short-Circuit Current		V _{L2IN} = 2.7V, V _{L2OUT} = GND	140	340	600	mA
Limit	ISHRT_LDO2	V _{L2IN} = 2.7V , V _{L2OUT} = GND, Switch mode	140	330	600	mA
Thermal-Shutdown Temperature	T _{SHDN_LDO2}			150		°C
Thermal-Shutdown Temperature Hysteresis	T _{SHDN_HYST_LDO2}			21		°C
		10Hz to 100kHz, V_{L2IN} = 5V, V_{L2OUT} = 3.3V		150		
Output Naige	OUT	10Hz to 100kHz, V _{L2IN} = 5V, V _{L2OUT} = 2.5V		125		11/4ma
Output Noise	OUT _{NOISE}	10Hz to 100kHz, V _{L2IN} = 5V, V _{L2OUT} = 1.2V		90		μVrms
		10Hz to 100kHz, V _{L2IN} = 5V, V _{L2OUT} = 0.9V		80		
L2IN UVLO	V	V _{L2IN} Falling	1.14	1.38		V
LZIN OVLO	V _{UVLO_LDO2}	V _{L2IN} Rising		1.4	1.64	, v
LDO3 (C = 1µF, unless otherwise	e noted. Typical values a	are at V _{L3IN} = 3.7V, with I _{L3OUT} = 10m <i>l</i>	4, V _{L3OUT} =	: 3V.)		
		LDO mode	1.71		5.5	V
Input Voltage	V _{INLDO3}	Switch mode	1.2		5.5	V
Quiescent Supply	1	I _{L3OUT} = 0μA		1	5.1	
Current	IQ_LDO3	I _{L3OUT} = 0μA, Switch mode		0.5		μA
Quiescent Supply Current in Dropout	I _{QDO_LDO3}	$I_{L3OUT} = 0\mu A$, $V_{L3IN} = 2.9V$, LDO3VSet = 3V.		1.8		μА
Shutdown Supply Current with Active Discharge Enabled	I _{SD_LDO3}	LDO3 disabled. LDO3ActDSC=1.		54		μА
Maximum Output		V _{L3IN} ≥ 2.7V	100			mA
Current	IL3OUT_MAX	V _{L3IN} = 1.8V or lower	50			mA
Output Voltage	V _{L3OUT}		0.9		4	V
Output Accuracy	ACC _{LDO3}	V_{L3IN} = (V_{L3OUT} + 0.5V) or higher, I_{L3OUT} = 100 μ A	-2.7		+2.7	%
Dropout Voltage	V _{DROP_LDO3}	V _{L3IN} = 3V, I _{L3OUT} = 100mA, LDO3VSet = 3V			100	mV

Electrical Characteristics (continued)

 $(V_{CHGIN} = 5.0V, V_{BAT} = 3.7V, T_A = -40^{\circ}C$ to +85°C, all registers in their default state, unless otherwise noted. Typical values are at $T_A = +25^{\circ}C$.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Line Regulation Error	V _{LINEREG_LDO3}	V _{L3IN} = (V _{L3OUT} + 0.5V) to 5.5V	-0.4	+0.05	+0.4	%/V
Load Regulation Error	V _{LOADREG_LDO3}	I _{L3OUT} = 100μA to 100mA		0.001	0.005	%/mA
Line Transient	\/	V _{L3IN} = 4V to 5V, 200ns rise time		±35		mV
Line transient	V _{LINETRAN_LDO3}	V _{L3IN} = 4V to 5V, 1µs rise time		±25		mV
Lood Transient	V	I _{L3OUT} = 0mA to 10mA, 200ns rise time		100		mV
Load Transient	VLOADTRAN_LDO3	I _{L3OUT} = 0mA to 100mA, 200ns rise time		200		mV
Passive Discharge Resistance	R _{PD_LDO3}		5	10	16	ΚΩ
Active Discharge Current	I _{ADL_LDO3}	V _{L3IN} = 3.7V	7	20	37	mA
		V _{L3IN} = 2.7V, I _{L3OUT} = 100mA		0.46	0.76	
Switch Mode Resistance	R _{ON_LDO3}	V _{L3IN} = 1.8V, I _{L3OUT} = 100mA		0.7	1.15	Ω
		V _{L3IN} = 1.2V, I _{L3OUT} = 5mA		1.7	2.6	
Turn-On Time	[†] ON_LDO3	I _{L3OUT} = 0mA, time from 10% to 90% of final value		1.5	3.7	
Turn-On Time		I _{L3OUT} = 0mA, time from 10% to 90% of final value, Switch mode		0.25	0.65	- ms
Short-Circuit Current		V _{L3IN} = 2.7V, V _{L3OUT} = GND	140	340	600	mA
Limit Current	ISHRT_LD03	V _{L3IN} = 2.7V , V _{L3OUT} = GND, Switch mode	140	330	600	mA
Thermal-Shutdown Temperature	T _{SHDN_LDO3}			150		°C
Thermal-Shutdown Temperature Hysteresis	T _{SHDN_HYST_LDO3}			21		°C
		10Hz to 100kHz, V _{L3IN} = 5V, V _{L3OUT} = 3.3V		150		
Outrout Naiss	OUT	10Hz to 100kHz, V _{L3IN} = 5V, V _{L3OUT} = 2.5V		125		
Output Noise	OUT _{NOISE}	10Hz to 100kHz, V _{L3IN} = 5V, V _{L3OUT} = 1.2V		80		μVrms
		10Hz to 100kHz, V _{L3IN} = 5V, V _{L3OUT} = 0.9V		60		
L3IN UVLO	V	V _{L3IN} Falling	1.14	1.38		V
LOIN UVLU	V _{UVLO_LDO3}	V _{L3IN} Rising		1.4	1.64	\ \ \

Electrical Characteristics (continued)

 $(V_{CHGIN} = 5.0V, V_{BAT} = 3.7V, T_A = -40^{\circ}C$ to +85°C, all registers in their default state, unless otherwise noted. Typical values are at $T_A = +25^{\circ}C$.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
CHGIN TO SYS PATH (V _{CHGIN} = 5.0V, V _{SYS} = V	/ _{SYS_REG})					
Allowed CHGIN Input Voltage Range	V _{CHGIN_RNG}		-5.5		28	V
V _{CHGIN} Detect Threshold	V _{CHGIN_DET}	Rising Falling	3.8	3.9 3.1	4.1 3.2	V
V _{CHGIN} Overvoltage Threshold	V _{CHGIN_OV}	Rising	7.2	7.5	7.8	V
V _{CHGIN} Overvoltage Threshold Hysteresis	Vchgin_ov_hys			200		mV
V _{CHGIN} Valid Trip Point	V _{CHGIN-SYS_TP}	V _{CHGIN} – V _{SYS} , Rising, V _{BAT} = 4V	+30	+145	+290	mV
V _{CHGIN} Valid Trip Point Hysteresis	VCHGIN-SYS_TP_HYS			275		mV
	I _{LIM}	ILimCntl[1:0] = 00		0		
Input Limiter Current		ILimCntl[1:0] = 01		90	100	mA
Input Limiter Current		ILimCntl[1:0] = 10		450	550	
		ILimCntl[1:0] = 11		1000		
Internal CAP Regulator	V _{CAP}	V _{CHGIN} = 5V	3.9	4.2	4.7	V
CHGIN-SYS Regulation Voltage	V _{CHGIN-SYS}	V _{CHGIN} = 4V, I _{SYS} = 1mA		40		mV
CHGIN to SYS On-Resistance	R _{CHGIN-SYS}	V _{CHGIN} = 4.4V, I _{SYS} = 500mA		370	660	mΩ
Thermal-Shutdown Temperature	T _{CHGIN_SHDN}	(Note 3)		+150		°C
Thermal-Shutdown Temperature Hysteresis	TCHGIN_SHDN_HYS			30		°C
Input Current Soft-Start Time	^t sfst_lim			1		ms
Internal Supply Switchover Threshold	V _{CCINT_TH}	$V_{CHGIN} = V_{CAP}$ rising, $V_{BAT} = 4.2V$	2.5	2.8	3.0	V

Electrical Characteristics (continued)

 $(V_{CHGIN} = 5.0V, V_{BAT} = 3.7V, T_A = -40^{\circ}C$ to +85°C, all registers in their default state, unless otherwise noted. Typical values are at $T_A = +25^{\circ}C$.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
SYS, BATTERY, AND VC			ļ			
	V _{SYSUVLO} R	Rising		2.64	2.69	V
SYS UVLO Threshold	V _{SYSUVLO_F}	Falling	2.57	2.62	2.67	V
SYS UVLO Threshold Hysteresis	V _{SYSUVLO_HYS}	Hysteresis		26		mV
SYS UVLO Falling Debounce Time	tsysuvlo_fdeb	SYS Falling		20		μs
V _{CCINT} UVLO Threshold (POR)	V _{UVLO}	V _{CCINT} Rising	0.8	1.82	2.6	V
V _{CCINT} UVLO Threshold Hysteresis	V _{UVLO_HYS}			140		mV
BAT UVLO Threshold	V _{BAT_UVLO}	Rising (Valid only when CHGIN is present. When V _{BAT} < V _{BAT_UVLO} , the BAT-SYS switch opens and BAT is connected to SYS through a diode.)	1.9	2.05	2.2	V
BAT UVLO Threshold Hysteresis	V _{BAT_UVLO_HYS}	Hysteresis		50		mV
BATTERY CHARGER (Se (V _{BAT} = 4.2V. Typical value						
Allowed BAT Voltage Range	V _{BAT_RNG}		0		5.5	V
BAT to SYS On-Resistance	R _{BAT-SYS}	V _{BAT} = 4.2V, I _{BAT} = 300mA		80	140	mΩ
Current Reduce Thermal Threshold Temperature	T _{CHG_LIM}	(Note 4)		120		°C
BAT-to-SYS Switch-On Threshold	V _{BAT-SYS-ON}	SYS falling	10	22	35	mV
BAT-to-SYS Switch-Off Threshold	V _{BAT-SYS-OFF}	SYS rising	-3	-1.5	0	mV
SYS-BAT Regulation Voltage	V _{SYS_REG}	V _{CHGIN} = 5V, I _{SYS} = 1mA	V _{BatReg} + 140mV	V _{BatReg} + 200mV	V _{BatReg} + 260mV	V

Electrical Characteristics (continued)

 $(V_{CHGIN} = 5.0V, V_{BAT} = 3.7V, T_A = -40^{\circ}C$ to +85°C, all registers in their default state, unless otherwise noted. Typical values are at $T_A = +25^{\circ}C$.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
		SysMin = 000, V _{BAT} > 3.6V		V _{BAT} + 0.1		
		SysMin = 000, V _{BAT} < 3.4V		3.6		
		SysMin = 001, V _{BAT} < 3.4V		3.7		
0.40 Ti		SysMin = 010, V _{BAT} < 3.4V		3.8		
SYS Threshold Voltage Charger Limiting Current (Note 5)	V _{SYS_LIM}	SysMin = 011, V _{BAT} < 3.4V		3.9		V
(1010 0)		SysMin = 100, V _{BAT} < 3.4V	3.86	4	4.14	
		SysMin = 101, V _{BAT} < 3.4V		4.1		
		SysMin = 110, V _{BAT} < 3.4V		4.2		
		SysMin = 111, V _{BAT} < 3.4V		4.3		
Charger Current Soft- Start Time	t _{CHG_SOFT}			1		ms
PRECHARGE						
		IPChg = 00		5		
Precharge Current	la acca	IPChg = 01	9	10	11	0/ 1
Precharge Current	lрснд	IPChg = 10		20		%I _{FChg}
		IPChg = 11		30		
		VPChg = 000		2.1		
		VPChg = 001	2.15	2.25	2.35	1
		VPChg = 010		2.40		
Prequalification		VPChg = 011		2.55		
Threshold	V_{BAT_PChg}	VPChg = 100		2.7		- V
		VPChg = 101		2.85		
		VPChg = 110		3.0		
		VPChg = 111		3.15		
Prequalification Threshold Hysteresis	V _{BAT_PChg_HYS}			90		mV

Electrical Characteristics (continued)

 $(V_{CHGIN} = 5.0V, V_{BAT} = 3.7V, T_A = -40^{\circ}C$ to +85°C, all registers in their default state, unless otherwise noted. Typical values are at $T_A = +25^{\circ}C$.) (Note 1)

PARAMETER	SYMBOL		CONDITIONS	MIN	TYP	MAX	UNITS	
FAST CHARGE								
SET Current Gain Factor	K _{SET}				2000		A/A	
SET Regulation Voltage	V _{SET}				1		V	
		R _{SET} = 400	DkΩ		5			
Fast-Charge Current	I _{FChg}	R _{SET} = 40k	(Ω	45	50	55	mA	
		R _{SET} = 4k0	Ω	450	500	550		
Fast-Charge Current Accuracy (Note 6)	I _{FChg_ACC}	R _{SET} Rang	ge = $4k\Omega$ to $40k\Omega$	-10		+10	%	
MAINTAIN CHARGE								
		ChgDone =	= 00		5			
Charge Done Qualification	la	ChgDone =	= 01	8.5	10	11.5	5 %1	
	I _{Chg_DONE}	ChgDone = 10		20		%I _{FChg}		
		ChgDone =	= 11		30			
		BatReg = 0000			4.05			
		BatReg = 0001			4.10			
		BatReg = 0	0010		4.15			
		BatReg =	T _A = +25°C	4.179	4.2	4.221		
		0011	$T_A = 0 \text{ to } +45C$	4.168	4.2	4.232		
DAT D		BatReg = 0)100		4.25			
BAT Regulation Voltage (Note 7)	V_{BatReg}	BatReg = 0)101		4.3		V	
()		BatReg = 0)110		4.35			
		BatReg = 0)111		4.4			
		BatReg = 1	1000		4.45			
		BatReg = 1	1001		4.5			
		BatReg = 1	BatReg = 1010		4.55		7	
		BatReg = 1	BatReg = 1011		4.6			
		BatReChg	= 00	,	√ _{BatReg} - 70)		
BAT Recharge	Vp. (p. c)	BatReChg	= 01	V	V _{BatReg} - 120			
Threshold	VBatReChg	BatReChg	BatReChg = 10		/ _{BatReg} -17	0	mV	
		BatReChg	<u> </u>		/ _{BatReg} -22	BatReg -220		

Electrical Characteristics (continued)

 $(V_{CHGIN} = 5.0V, V_{BAT} = 3.7V, T_A = -40^{\circ}C$ to +85°C, all registers in their default state, unless otherwise noted. Typical values are at $T_A = +25^{\circ}C$.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
CHARGER TIMER						
		PChgTmr = 00		30		
Maximum		PChgTmr = 01		60		Ī
Prequalification Time	t _{PChg}	PChgTmr = 10		120		min
		PChgTmr = 11		240		
	4	FChgTmr = 00		75		
Maximum Fast-Charge		FChgTmr = 01		150		
Time	t _{FChg}	FChgTmr = 10		300		min
		FChgTmr = 11		600		1
		TOChgTmr = 00		0		
Maintain Obana Tina	_	TOChgTmr = 01		15		
Maintain-Charge Time	tTOChg	TOChgTmr = 10		30		– min
		TOChgTmr = 11		60		
Timer Accuracy	tCHG_ACC		-10		+10	%
Timer Extend Threshold	TIM _{EXD_} THRES	If charge current is reduced due to ILIM or TDIE this is the percentage of charge current below which timer clock operates at half speed		50		%I _{FChg}
Timer Suspend Threshold	TIM _{SUS_THRES}	If charge current is reduced due to ILIM or TDIE this is the percentage of charge current below which timer clock pauses		20		%I _{FChg}
THERMISTOR MONITOR	AND NTC DETECTION	DN				
THM Hot Threshold	_	V _{THM} falling, MAX14745A/ MAX14745C	30.9	32.9	34.9	
THIN HOLTHIESHOID	T ₄	V _{THM} falling, MAX14745D/ MAX14745E	21.3	23.3	25.3	
TUNA VA/como Ticoco de cid	_	V _{THM} falling, MAX14745A/ MAX14745C	48	50	52	%CAP
THM Warm Threshold	T ₃	V _{THM} falling, MAX14745D/ MAX14745E	30.9	32.9	34.9	
THM Cool Threshold	T ₂	V _{THM} rising	62.5	64.5	66.5	
THM Cold Threshold	T ₁	V _{THM} rising	71.9	73.9	75.9	
THM Disable Threshold	THM _{DIS}	V _{THM} rising	91	93	95	
THM Threshold Hysteresis	THM _{HYS}			60		mV
THM Input Leakage	I _{LKG_THM}		-1		1	μA
						_

Electrical Characteristics (continued)

 $(V_{CHGIN} = 5.0V, V_{BAT} = 3.7V, T_A = -40^{\circ}C$ to +85°C, all registers in their default state, unless otherwise noted. Typical values are at $T_A = +25^{\circ}C$.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
START UP TIMING (See F	igure 2)					
		BootDly = 00		80		
Do at Dalan		BootDly = 01		120		Ī
Boot Delay	^t RST	BootDly = 10		220		- ms
		BootDly = 11		420		
Boot Delay Timer Accuracy	trst_acc		-10		10	%
DIGITAL SIGNALS						
Input Logic-High (SDA, SCL, MPC0, MPC1, PFN1, PFN2)	V_{IH}		1.4			V
Input Logic-Low (SDA, SCL, MPC0, MPC1, PFN1, PFN2)	V _{IL}				0.5	V
Output Logic-Low (SDA, RST, INT, LED, PFN2)	V _{OL}	I _{OL} = 4mA			0.4	V
High Level Leakage Current (SDA, RST, INT, LED, PFN2)	I _{LK}				1	μА
SCL Clock Frequency	f _{SCL}				400	kHz
Bus Free Time Between a STOP and START Condition	^t BUF		1.3			μs
START Condition (Repeated) Hold Time	t _{HD:STA}	(Note 8)	0.6			μs
Low Period of SCL Clock	t_{LOW}		1.3			μs
High Period of SCL Clock	^t HIGH		0.6			μs
Setup Time for a Repeated START Condition	tsu:sta		0.6			μs
Data Hold Time	t _{HD:DAT}	(Note 9)	0		0.9	μs
Data Setup Time	t _{SU:DAT}	(Note 9)	100			ns
Setup Time for STOP Condition	t _{SU:STO}		0.6			μs
Spike Pulse Widths Suppressed by Input Filter	t _{SP}	(Note 10)		50		ns

MAX14745

PMIC with Ultra Low I_Q Voltage Regulators and Battery Charger for Small Lithium Ion Systems

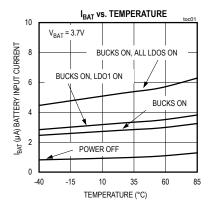
Electrical Characteristics (continued)

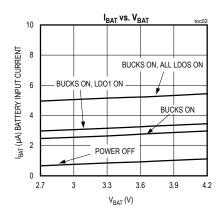
 $(V_{CHGIN} = 5.0V, V_{BAT} = 3.7V, T_A = -40^{\circ}C$ to +85°C, all registers in their default state, unless otherwise noted. Typical values are at $T_A = +25^{\circ}C$.) (Note 1)

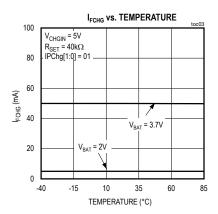
- Note 1: All devices are 100% production tested at T_A = +25°C. Limits over the operating temperature range guaranteed by design.
- **Note 2:** This value is included in the I_{BAT} quiescent current values for the ON states.
- Note 3: When the die temperature exceeds T_{CHGIN} SHDN, the CHGIN to SYS path opens, and the charger is turned off.
- **Note 4:** When the die temperature exceeds T_{CHG} L_{IM}, the charger current starts to decrease.
- Note 5: This is the threshold at which the charger starts to limit the current due to SYS dropping; if VSYS drops below this value the charger will not move to maintain charge.
- Note 6: Fast charge current accuracy tested only at 50mA and 500mA, all other values guaranteed by design.
- **Note 7:** Values over temperature are not production tested and guaranteed by characterization.
- **Note 8:** f_{SCI} must meet the minimum clock low time plus the rise/fall times.
- Note 9: The maximum t_{HD:DAT} has to be met only if the device does not stretch the low period (t_{I OW}) of the SCL signal.
- Note 10: Filters on SDA and SCL suppress noise spikes at the input buffers and delay the sampling instant.

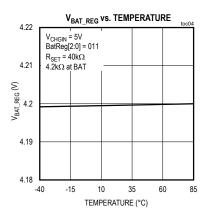
Typical Operating Characteristics

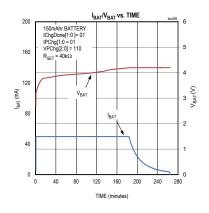
 $(V_{BAT} = 3.7V, V_{CHGIN} = 0V, registers in their default state, T_A = +25$ °C, unless otherwise noted.)

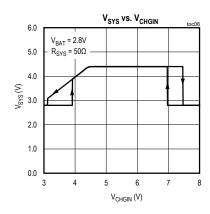


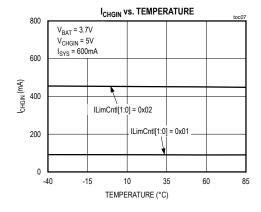


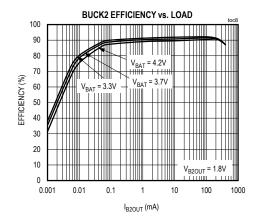






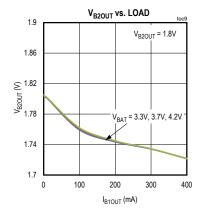


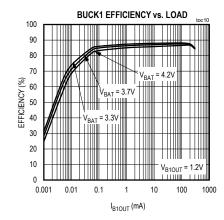


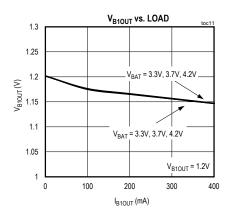


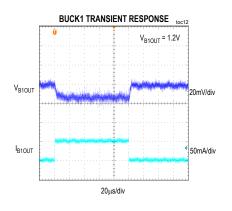
Typical Operating Characteristics (continued)

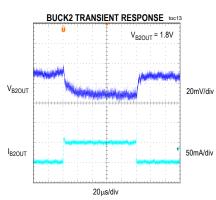
 $(V_{BAT} = 3.7V, V_{CHGIN} = 0V, registers in their default state, T_A = +25$ °C, unless otherwise noted.)

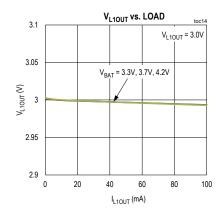


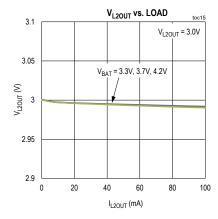


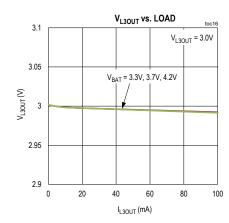


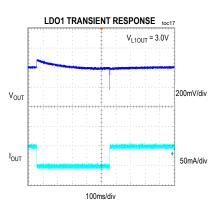






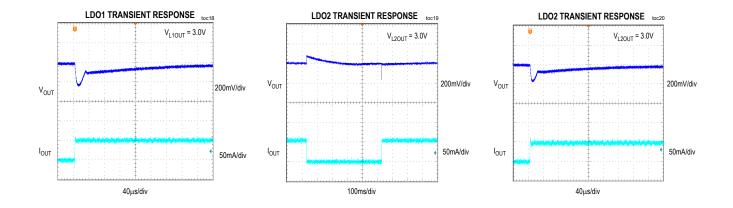


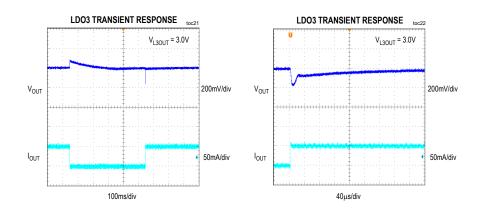




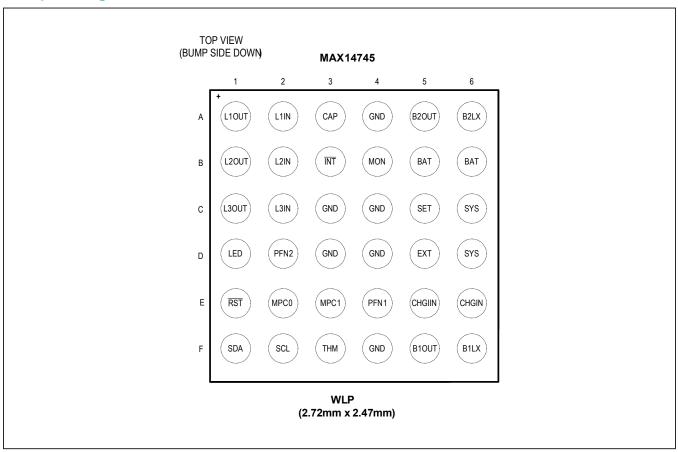
Typical Operating Characteristics (continued)

(V_{BAT} = 3.7V, V_{CHGIN} = 0V, registers in their default state, T_A = +25°C, unless otherwise noted.)





Bump Configuration



Bump Description

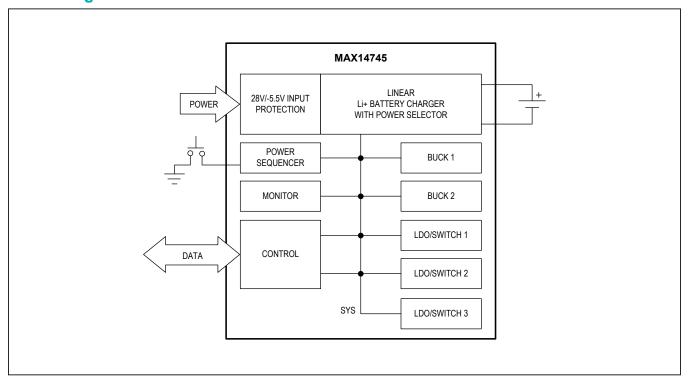
BUMP	NAME	FUNCTION
A1	L10UT	LDO1 Output. Bypass with a minimum 1µF capacitor to GND.
A2	L1IN	LDO1 Input
A3	CAP	Bypass for Internal LDO. Bypass with a 1µF capacitor to GND.
A4, C3, C4 D3, D4, F4	GND	Ground
A5	B2OUT	0.8V – 3.95V Buck Regulator Output Feedback. Bypass with a 10μF capacitor to GND.
A6	B2LX	0.8V – 3.95V Buck Regulator Switch. Connect 2.2μH inductor to B2OUT.
B1	L2OUT	LDO2 Output. Bypass with a minimum 1µF capacitor to GND.
B2	L2IN	LDO2 Input
В3	ĪNT	Open-Drain, Active-Low Interrupt Output.
B4	MON	Voltage Monitor Pin
B5,B6	BAT	Battery Connection. Connect BAT to a positive battery terminal, bypass BAT with a minimum 1µF capacitor to GND.

Bump Description (continued)

PIN	NAME	FUNCTION
C1	L3OUT	LDO3 Output. Bypass with a minimum 1µF capacitor to GND.
C2	L3IN	LDO3 Input
C5	SET	External Resistor For Battery Charge Current Level Setting. Do not connect any external capacitance on this pin; maximum allowed capacitance (C _{SET} < 5µs/R _{SET}) pF.
C6, D6	SYS	System Load Connection. Connect SYS to the system load. Bypass SYS with a minimum 10µF low-ESR ceramic capacitor to GND.
D1	LED	LED Open-Drain Pulldown Current. Add an external current limiting pullup resistor.
D2	PFN2	Power Function Control Input/Output. Programmable functionality via PwrFnMode. See Table 1.
D5	EXT	Push-Pull Gate Drive for Optional External pFET from BAT-to-SYS. Output is pulled to GND when charger is disconnected and internal BAT-SYS FET is switched on. Otherwise, this output is pulled high to the SYS voltage.
E1	RST	Power-On Reset Output. Active-low, open-drain.
E2	MPC0	Multipurpose Configuration Input 0
E3	MPC1	Multipurpose Configuration Input 1
E4	PFN1	Power Function Control Input. Programmable functionality via PwrFnMode. See Table 1.
E5, E6	CHGIN	-5.5V/+28V Protected Charger Input. Bypass CHGIN with 1µF capacitor to GND.
F1	SDA	Open-Drain, I ² C Serial Data Input/Output.
F2	SCL	I ² C Serial Clock Input
F3	THM	Battery Temperature Thermistor Measurement Connection. Connect a $10k\Omega$ resistor from THM to CAP and a $10k\Omega$, 3380β NTC thermistor from THM to GND.
F5	B1OUT	0.8V – 2.375V Buck Regulator Output Feedback. Bypass B1OUT with a 10μF capacitor to GND.
F6	B1LX	0.8V – 2.375V Buck Regulator Switch Terminal. Connect B1LX to B1OUT with a 2.2µH inductor.

Note: All capacitance values listed in this document refer to effective capacitance. Be sure to specify capacitors that will meet these requirements under typical system operating conditions taking into consideration the effects of voltage and temperature.

Block Diagram



Detailed Description

Power Regulation

The MAX14745 family includes two high-efficiency, low quiescent current buck regulators, and three low quiescent current linear regulators that are also configurable as power switches. Excellent light-load efficiency allows the switching regulators to run continuously without significant energy cost.

Power On/Off and Reset Control

The behavior of power function control pins (PFN1 and PFN2) is preconfigured to support one of the multiple types of wearable application cases. <u>Table 1</u> describes the behavior of the PFN1 and PFN2 pins based on the PwrRstCfg[3:0] bits and <u>Figure 1</u> shows basic flow diagrams associated with each mode.

A Soft-Reset generates a 10ms logic low pulse at $\overline{\text{RST}}$ and resets all registers to their default values. A Hard-Reset initiates a complete Power-On Reset sequence and generates a 50ms logic-low pulse at $\overline{\text{RST}}$.

Table 1. Power Function Input Control Modes

PwrRstCfg[3:0]**	PFN1**	PFN1 PU/PD	PFN2**	PFN2 PU/PD		able Pwi	Cmd			
พากรเอเชเรเ.บ]		PFNxResEna = 1		PFNxResEna = 1	OFF	HARD	SOF			
	ENABLE	PULLDOWN	Manual Reset	PULLUP*	NO	NO	YES			
On/Off	On/Off Mode with 10ms debounce. PFN1 is the active-high on/off control input. PFN2 is the active-low soft-reset input.									
	DISABLE	PULLUP*	Manual Reset	PULLUP*	NO	NO	YES			
On/Off	On/Off Mode with 10ms input.	debounce. PFN1 is	s the active-low on/off c	control. PFN2 is the	active-lov	w soft-res	et			
	Hard-Reset on PFN1 Rising	PULLDOWN	Soft-Reset on PFN2 Rising	PULLDOWN	YES	YES	YES			
AON	Always-On Mode. A risir generates a soft-reset a the PwrCmd register.				_	-				
	Hard-Reset on PFN1 Falling	PULLUP*	Soft-Reset on PFN2 Falling	PULLUP*	YES	YES	YES			
AON	Always-On Mode. A falli generates a soft-reset a the PwrCmd register.			•	_	-				
OD Hint	Hard-Reset on CHGIN insertion When PFN1 High	PULLDOWN	Soft-Reset CHGIN Insertion When PFN2 High	PULLDOWN	YES	YES	YES			
CR High	Charger Reset High Mode. When PFN1 is high, a CHGIN insertion generates a hard-reset after a 200ms delay. When PFN2 is high, a CHGIN insertion generates a soft-reset after a 200ms delay. In this mode, the device can only enter the off state by writing to the PwrCmd register.									
OD L	Hard-Reset on CHGIN Insertion When PFN1 low	PULLUP*	Soft-Reset on CHGIN Insertion When PFN2 Low	PULLUP*	YES	YES	YES			
CR Low	Charger Reset Low Mode. When PFN1 is low, a CHGIN insertion generates a Hard-Reset after a 200ms delay. When PFN2 is low, a CHGIN insertion generates a Soft-Reset after a 200ms delay. In this mode, the device can only enter the off state by writing to the PwrCmd register.									
	KIN	PULLUP*	KOUT	NONE	YES	YES	YES			
KIN	Custom Button Mode. P buffers the KIN input. The PwrCmd register. A CHC	ne device can enter	the off state by either a	a KIN press (>12s)						
	KIN	PULLUP*	KOUT	NONE	YES	NO	NO			
CSR1	Custom Soft Reset 1. P buffers the KIN input. A through the PwrCmd re	KIN press (>12s) ge	enerates a soft-reset. T	he device can only	enters th					
	KIN	PULLUP*	Manual Reset	NONE	YES	YES	YES			
CSR2	Custom Soft-Reset 2. P press (>12s) generates PwrCmd register.									

^{*} Pullup is connected to an internal supply, V_{CCINT} . ($V_{CCINT} = V_{CAP}$ if $V_{CAP} > V_{CCINT_TH}$, or V_{CCINT_TH} if $V_{CAP} < V_{CCINT_TH}$).

** PwrRstCfg[3:0] is read-only; the functions of PFN1 and PFN2 cannot be changed through I^2C

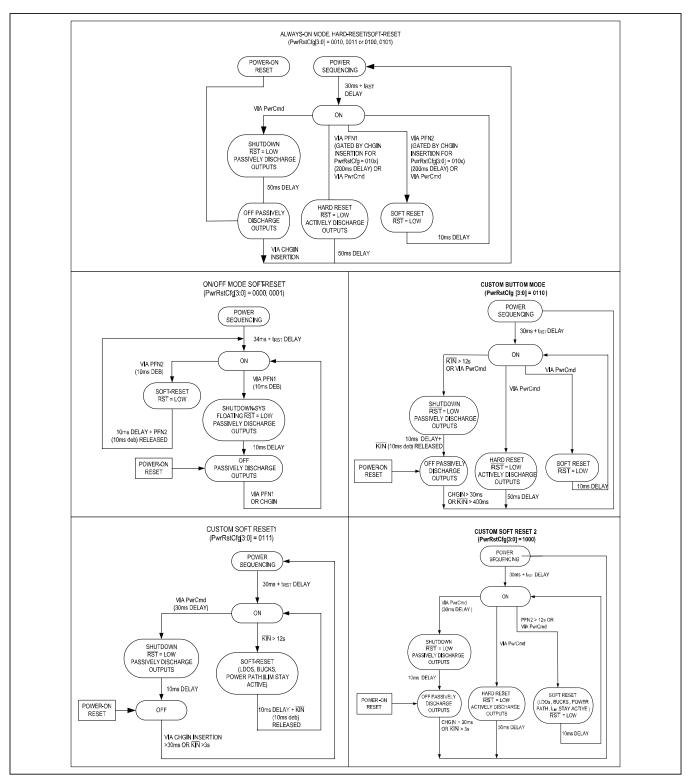


Figure 1. Power Function Input Control Modes Flow Diagrams

Power Sequencing

There are multiple configuration options for the sequencing of the buck regulators and LDOs during power-on. See $\underline{\text{Table 1}}$ for details. Regulators can be configured to turn on at one of the four points during the power-on process: 0% $t_{RST}, 25\%$ $t_{RST}, 50\%$ $t_{RST},$ and 100% $t_{RST}.$ The reset delay t_{RST} can be set to 80ms, 120ms, 220ms, or 420ms by BootDly[1:0] in the BootCfg register. The power-on sequencing is depicted in Figure 2a and Figure 2b.

Additionally, the regulators can be selected to default off and can be turned on with an I²C command after RST is released. Each LDO regulator can be configured to be always-on as long as SYS or BAT is present.

In general, if an undervoltage condition is detected on SYS the device goes into the off state. However if there is a valid voltage on CHGIN the behavior is determined by the ChgAlwTry setting. If ChgAlwTry = 0, and an undervoltage condition is detected on SYS during the sequencing process the device turns SYS and all other external resources off and waits for CHGIN removal. On CHGIN removal the device enters the off state to avoid draining the battery. If ChgAlwTry = 1, the process will continually recheck the SYS undervoltage condition every 500ms until it is no longer vaild before continuing with the sequencing process.

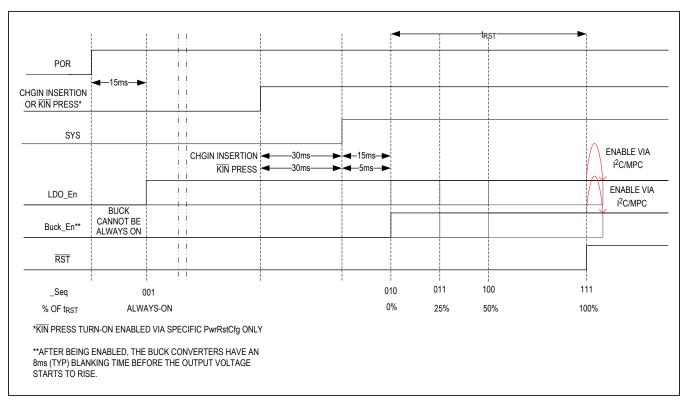


Figure 2a. Power-On Sequencing

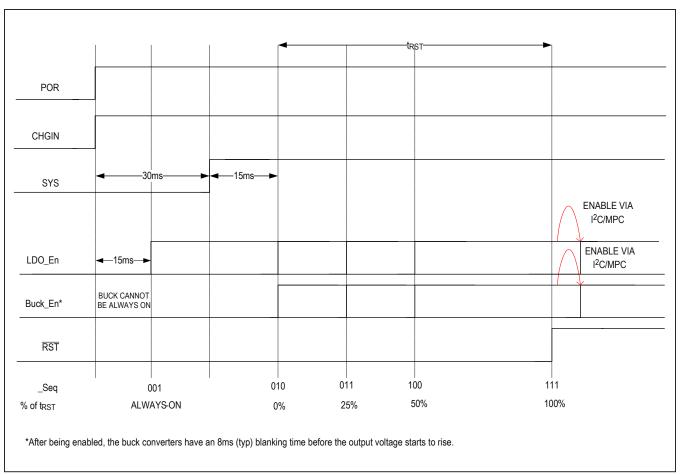


Figure 2b. Power-On Sequencing Without Battery

Smart Power Selector

The smart power selector seamlessly distributes power from the external CHGIN input to the battery (BAT) and the system (SYS). With both an external adapter and battery connected, the smart power selector basic functions are:

- When the system load requirements are less than the input current limit, the battery is charged with residual power from the input.
- When the system load requirements exceed the input current limit, the battery supplies supplemental current to the load.

 When the battery is connected and there is no external power input, the system is powered from the battery.

Thermal Current Regulation

In case the die temperature exceeds the normal limit, the MAX14745 will attempt to limit the temperature increase by reducing the input current from CHGIN. In this condition, the system load has priority over charger current, so the input current is first reduced by lowering the charge current. If the junction temperature continues to rise and reaches the maximum operating limit, no input current is drawn from CHGIN and the battery powers the entire system load.

System Load Switch

An internal $80m\Omega$ (typ) MOSFET connects SYS to BAT when no voltage source is available on CHGIN. When an external source is detected at CHGIN, this switch opens and SYS is powered from the input source through the input current limiter. The SYS-to-BAT switch also prevents VSYS from falling below VBAT when the system load exceeds the input current limit. If VSYS drops to VBAT due to the current limit, the load switch turns on so the load is supported by the battery. If the system load continuously exceeds the input current limit the battery is not charged. This is useful for handling loads that are nominally below the input current limit but have high current peaks exceeding the input current limit. During these peaks, battery energy is used, but at all other times the battery charges. See Figure 3.

The pin EXT can drive the gate of an external pMOS connected between SYS (source, bulk) and BAT (drain) in parallel to the internal one.

When V_{CHGIN} < V_{BDET} the EXT voltage is the buffered version of the internal gate command that controls the internal $80m\Omega$ (typ) MOSFET.

Note: The body diode of an external pMOS connected between BAT and SYS remains present when the device is in off mode.

Input Limiter

The input limiter distributes power from the external adapter to the system load and battery charger. In addition to the input limiter's primary function of passing power to the system load and charger, it performs several additional functions to optimize use of available power:

Invalid CHGIN Voltage Protection: If CHGIN is above the overvoltage threshold, the MAX14745 enters overvoltage lockout (OVL). OVL protects the MAX14745 and downstream circuitry from high-voltage stress up to 28V and down to -5.5V. During OVL, the internal circuit remains powered and an interrupt is sent to the host. During OVL, the charger turns off and the system load switch closes, allowing the battery to power SYS. CHGIN is also invalid if it is less than VBAT, or less than the USB undervoltage threshold. With an invalid input voltage, the SYS-to-BAT load switch closes and allows the battery to power SYS.

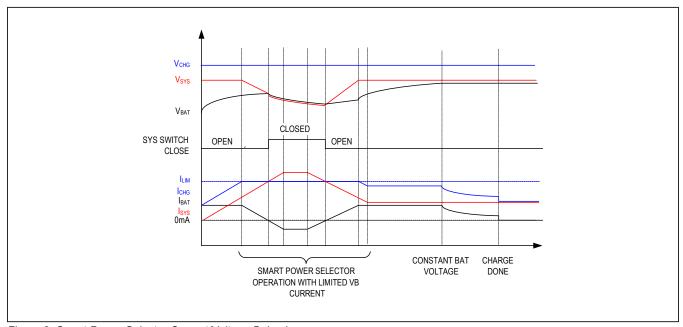


Figure 3. Smart Power Selector Current/Voltage Behavior

CHGIN Adaptive Input Current Limit: The CHGIN input current is limited to prevent input overload. The input current limit is controlled by I²C. However, if the voltage at CHGIN collapses because the source is not able to supply either the current programmed in I²C, or the total current required by the battery charger and system load, the input current limit will be adaptively reduced.

Thermal Limiting: In case the die temperature exceeds the normal limit (T_{CHG_LIM}), the MAX14745 attempts to limit temperature increase by reducing the input current from CHGIN. In this condition, the system load has priority over the charger current, so the input current is first reduced by lowering the charge current. If the junction temperature continues to rise and reaches the maximum operating limit (T_{CHGIN_SHDN}), no input current is drawn from CHGIN and the battery powers the entire system load.

Adaptive Battery Charging: While the system is powered from CHGIN, the charger draws power from SYS to charge the battery. If the total load exceeds the input current limit, an adaptive charger control loop reduces charge current to prevent V_{SYS} from collapsing.

When the charge current is reduced below 50% due to I_{LIM} or T_{DIE} , the timer clock operates at half speed. When the charge current is reduced below 20% due to I_{LIM} or T_{DIE} , the timer clock is paused.

Fast-Charge Current Setting

The MAX14745 uses an external resistor connected from SET to GND to set the fast-charge current. The pre-charge and charge-termination currents are programmed as a percentage of this value through I²C registers. The fast-charge current resistor can be calculated as:

R_{SET} = K_{SET} x V_{SET}/I_{FChq}

where K_{SET} has a typical value of 2000A/A and V_{SET} has a typical value of 1V. The range of acceptable resistors for R_{SET} is $4k\Omega$ to $400k\Omega$

Thermistor Monitoring with Charger Shutdown

The MAX14745 features three modes for controlling charger behavior based on battery-pack temperature: Thermistor Monitoring, JEITA Monitoring 1, and JEITA Monitoring 2. The divider formed by a pull-up resistor (RPU) to CAP, optional parallel resistor (RPA) from THM to ground, and NTC thermistor (RTHM) from THM to ground, provides a voltage at THM that is proportional to temperature as a fraction of the CAP voltage. Two sets of preconfigured default thresholds (0°C/10°C/45°C/60°C or 0°C/10°C/25°C/45°C as a %CAP) optimized for beta 3380 thermistors are available (see Table 38). The four default thresholds create five temperature zones, and the fractional CAP voltage measured at the THM pin is compared to the thresholds to determine the active temperature zone during operation.

The behavior in each temperature zone is determined by the configuration of bits in the I²C registers. The active monitoring mode is selected by ThermEn[1:0] in the ThrmCfrg register. In all modes, the T2IFchg[2:0] and T2T3IFchg[2:0], and T3T4IFchg[2:0] fields in the ThrmCfg registers set the fast charge current in three temperature zones, T1 T2, T2 T3, and T3 T4. In Thermistor Monitoring mode, charging is enabled only in T1_T2 and T2 T3 and the battery termination voltage is equal to V_{BATREG}, as shown in <u>Figure 4a</u>. In both JEITA Monitoring 1 and JEITA Monitoring 2 the charger is active in the T1 T2, T2 T3, and T3 T4 zones. However, JEITA Monitoring 1 sets the battery termination voltage to VBATREG for all zones, while JEITA Monitoring 2 sets the battery termination voltage to VBATREG - 150mV for zones T1_2 and T3_T4, as shown in Figure 4b. The behavior of all three modes is summarized in Table 2.

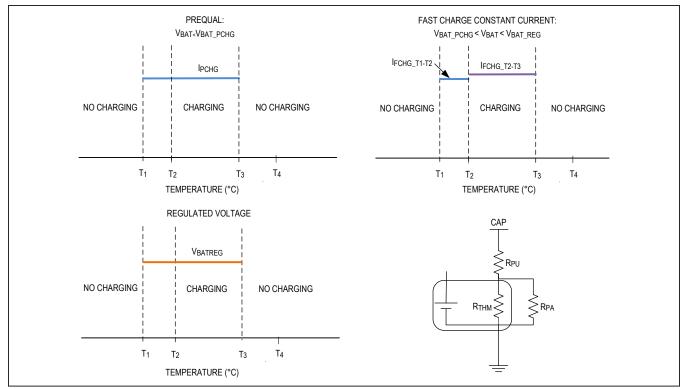


Figure 4a. Charging Behavior Using Thermistor Monitoring Mode

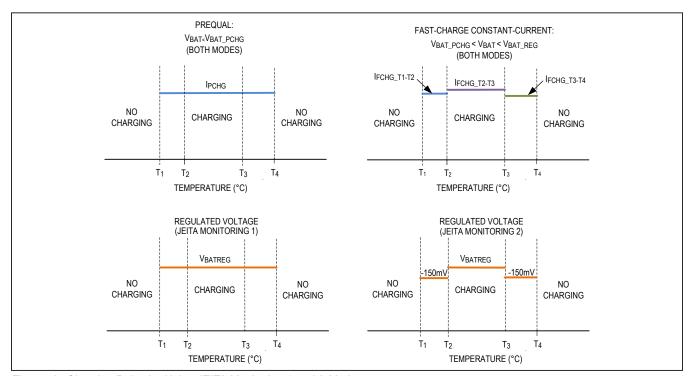


Figure 4b. Charging Behavior Using JEITA Monitoring 1 and 2 Modes

Table 2. Thermistor Monitoring/JEITA Monitoring Enable Control

Th a res E to [4 : 0]	DESCRIPTION			CHARGER MODE		
ThermEn[1:0]	DESCRIPTION	T < T1	T1 < T < T2	T2 < T < T3	T3 < T < T4	T >T4
00	Thermistor/ JEITA Monitoring OFF			As per I ² C settings		
01	Thermistor Monitoring ON	OFF	I _{PCHG} = IPChg, I _{FChg} = T1T2IFchg, Regulated Voltage = VBATREG	I _{PCHG} = IPChg, I _{FChg} = T2T3IFchg, Regulated Voltage = V _{BATREG}	OFF	OFF
10	JEITA Monitoring 1 ON	OFF	I _{PCHG} = IPChg, I _{FChg} = T1T2IFchg, Regulated Voltage = V _{BATREG}	I _{PCHG} = IPChg, I _{FChg} = T2T3IFchg Regulated Voltage = V _{BATREG}	I _{PCHG} = IPChg, I _{FChg} = T3T4IFchg Regulated Voltage = V _{BATREG}	OFF
11	JEITA Monitoring 2 ON	OFF	I _{PCHG} = IPChg, I _{FChg} = T1T2IFchg, Regulated Voltage = V _{BATREG} - 150mV	I _{PCHG} = IPChg, I _{FChg} = T2T3IFchg, Regulated Voltage = V _{BATREG}	I _{PCHG} = IPChg, I _{FChg} = T3T4IFchg, Regulated Voltage = V _{BATREG} - 150mV	OFF

I²C Interface

The device uses the two-wire I²C interface to communicate with the host microcontroller. The configuration settings and status information provided through this interface are detailed in the register descriptions.

I²C Addresses

The registers of the MAX14745 are accessed through the slave address of 0101000 (0x50 for writes/0x51 for reads).

Thermistor Monitoring with Charger Shutdown

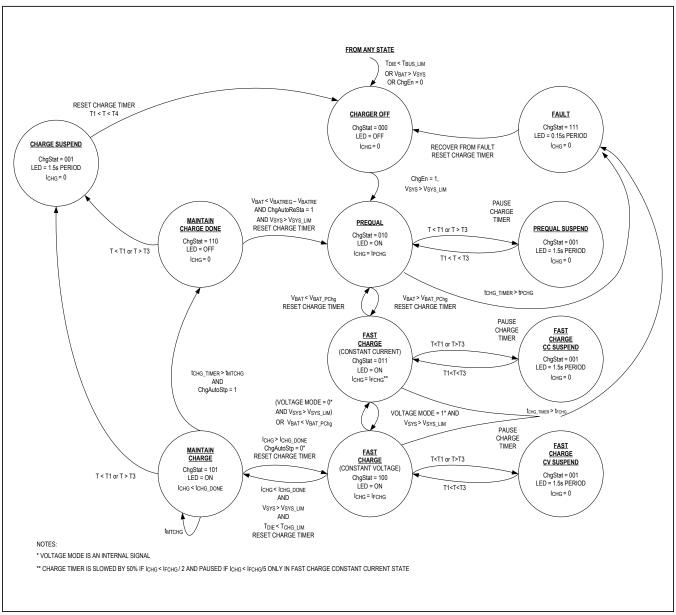


Figure 5a. Charger State Diagram (Thermistor Monitoring with Charger Shutdown)

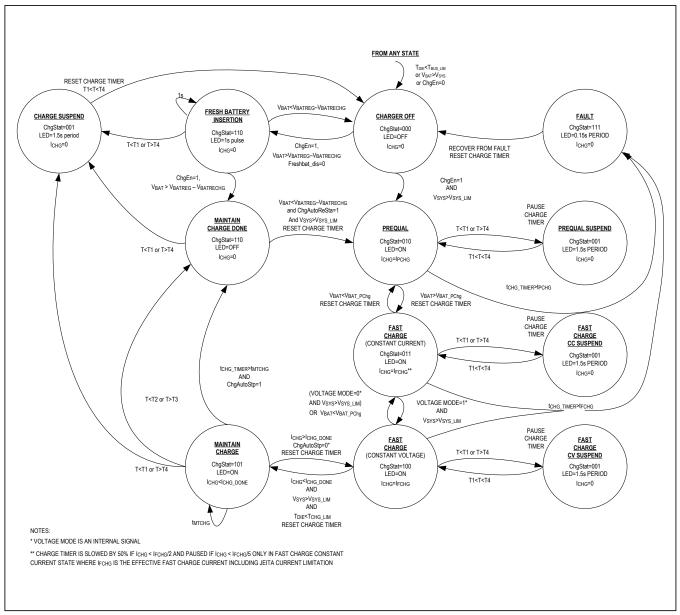


Figure 5b. Battery Charger State Diagram (JEITA Monitoring with Charger Shutdown)

I²C Interface

The MAX14745 contain an I²C-compatible interface for data communication with a host controller (SCL and SDA). The interface supports a clock frequency of up to 400kHz. SCL and SDA require pullup resistors that are connected to a positive supply.

Start, Stop, And Repeated Start Conditions

When writing to the MAX14745 using I²C, the master sends a START condition (S) followed by the MAX14745 I²C address. After the address, the master sends the register address of the register that is to be programmed. The master then ends communication by issuing a STOP condition (P) to relinquish control of the bus, or a REPEATED START condition (Sr) to communicate to another I²C slave. See Figure 6.

Table 3. I²C Slave Addresses

ADDRESS FORMAT	HEX	BINARY
7-Bit Slave ID	0x28	0101000
Write Address	0x50	01010000
Read Address	0x51	01010001

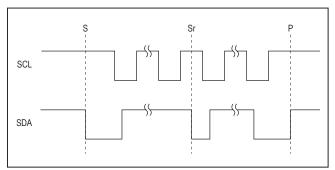


Figure 6. I²C START, STOP and REPEATED START Conditions

Slave Address

Set the Read/Write bit high to configure the MAX14745 to read mode (Table 3). Set the Read/Write bit low to configure the MAX14745 to write mode. The address is the first byte of information sent to the MAX14745 after the START condition.

Bit Transfer

One data bit is transferred on the rising edge of each SCL clock cycle. The data on SDA must remain stable during the high period of the SCL clock pulse. Changes in SDA while SCL is high and stable are considered control signals (see the <u>Start, Stop, And Repeated Start Conditions</u> section). Both SDA and SCL remain high when the bus is not active.

Single-Byte Write

In this operation, the master sends an address and two data bytes to the slave device (Figure 7). The following procedure describes the single byte write operation:

- 1) The master sends a START condition
- The master sends the 7-bit slave address plus a write bit (low)
- 3) The addressed slave asserts an ACK on the data line
- 4) The master sends the 8-bit register address
- 5) The slave asserts an ACK on the data line only if the address is valid (NAK if not)
- 6) The master sends 8 data bits
- 7) The slave asserts an ACK on the data line
- 8) The master generates a STOP condition

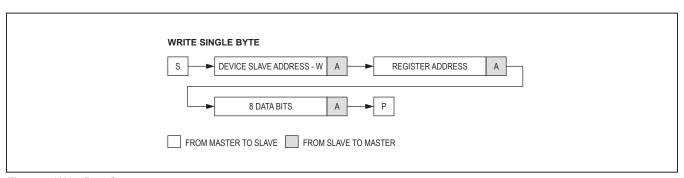


Figure 7. Write Byte Sequence

Burst Write

In this operation, the master sends an address and multiple data bytes to the slave device (Figure 8). The slave device automatically increments the register address after each data byte is sent. The following procedure describes the burst write operation:

- 1) The master sends a START condition
- The master sends the 7-bit slave address plus a write bit (low)
- 3) The addressed slave asserts an ACK on the data line
- 4) The master sends the 8-bit register address
- 5) The slave asserts an ACK on the data line only if the address is valid (NAK if not)
- 6) The master sends eight data bits
- 7) The slave asserts an ACK on the data line
- 8) Repeat 6 and 7 N-1 times
- 9) The master generates a STOP condition

Single Byte Read

In this operation, the master sends an address plus two data bytes and receives one data byte from the slave device (<u>Figure 9</u>). The following procedure describes the single byte read operation:

- 1) The master sends a START condition
- The master sends the 7-bit slave address plus a write bit (low)
- The addressed slave asserts an ACK on the data line
- 4) The master sends the 8-bit register address
- 5) The slave asserts an ACK on the data line only if the address is valid (NAK if not)
- 6) The master sends a REPEATED START condition
- 7) The master sends the 7-bit slave address plus a read bit (high)
- 8) The addressed slave asserts an ACK on the data line
- 9) The slave sends eight data bits
- 10) The master asserts a NACK on the data line
- 11) The master generates a STOP condition

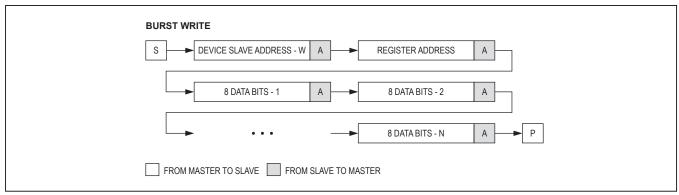


Figure 8. Burst Write Sequence

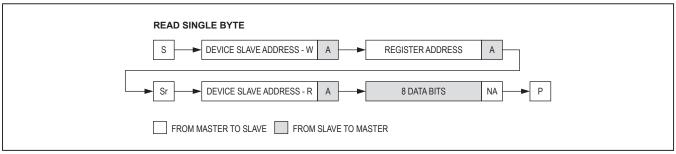


Figure 9. Read Byte Sequence

Burst Read

In this operation, the master sends an address plus two data bytes and receives multiple data bytes from the slave device (<u>Figure 10</u>). The following procedure describes the burst byte read operation:

- 1) The master sends a START condition
- 2) The master sends the 7-bit slave address plus a write bit (low)
- 3) The addressed slave asserts an ACK on the data line
- 4) The master sends the 8-bit register address
- 5) The slave asserts an ACK on the data line only if the address is valid (NAK if not)
- 6) The master sends a REPEATED START condition
- The master sends the 7-bit slave address plus a read bit (high)
- 8) The slave asserts an ACK on the data line

- 9) The slave sends eight data bits
- 10) The master asserts an ACK on the data line
- 11) Repeat 9 and 10 N-2 times
- 12) The slave sends the last eight data bits
- 13) The master asserts a NACK on the data line
- 14) The master generates a STOP condition

Acknowledge Bits

Data transfers are acknowledged with an acknowledge bit (ACK) or a not-acknowledge bit (NACK). Both the master and the MAX14745 generate ACK bits. To generate an ACK, pull SDA low before the rising edge of the ninth clock pulse and hold it low during the high period of the ninth clock pulse (see Figure 11). To generate a NACK, leave SDA high before the rising edge of the ninth clock pulse and leave it high for the duration of the ninth clock pulse. Monitoring for NACK bits allows for detection of unsuccessful data transfers.

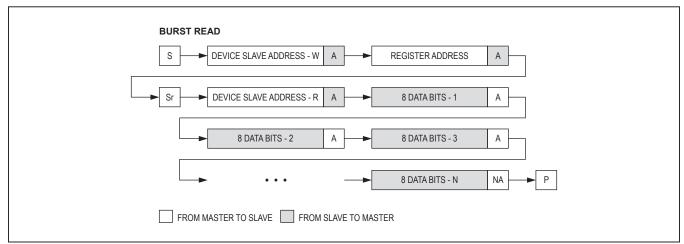


Figure 10. Burst Read Sequence

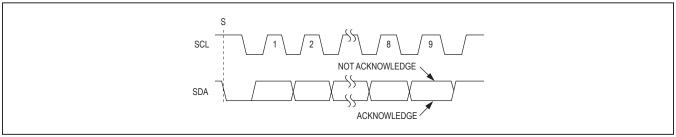


Figure 11. Acknowledge

MAX14745

PMIC with Ultra Low I_Q Voltage Regulators and Battery Charger for Small Lithium Ion Systems

I2C Register Map

REGISTER ADDRESS	REGISTER NAME	R/W	B7	B6	B5	B4	B3	B2	B	B0
00×0	ChipId	œ				Chip_ld[7:	Chip_ld[7:1,0] (Read-Only)			
0x01	ChipRev	œ				Chip_Rev[Chip_Rev[7:0] (Read-Only)			
0x02	StatusA	œ	I	I		JeitaStat[2:0]			ChgStat[2:0]	
0x03	StatusB	~	UVLOLD02	UVLOLDO3	lLim	UsbovP	UsbOk	ThrmSd	ChgThrmReg	ChgTmo
0x04	StatusC	œ	I	SysBatLim	ChgSysLim	ThrmBk1	ThrmBk2	ThrmLD01	ThrmLD02	ThrmLD03
0×05	IntA	COR	ThermStatInt	ChgStatInt	lLimlnt	UsbOVPInt	UsbOkInt	ChgThrm SdInt	ChgThrm RegInt	ChgTmoInt
90×0	IntB	COR	I	SysBatLimInt	ChgSys LimInt	ThrmBk1Int	ThrmBk2Int	ThrmLDO1Int	ThrmLDO2Int	ThrmLDO3Int
0x07	IntMaskA	R/W	Therm StatIntM	ChgStatIntM	ILimIntM	UsbOVPIntM	UsbOkIntM	ChgThrm SdIntM	ChgThrm RegIntM	ChgTmoIntM
0×08	IntMaskB	R/W	I	SysBatLim IntM	ChgSysLim IntM	ThrmBk1IntM	Thrm Bk2IntM	Thrm LDO1IntM	Thrm LDO2IntM	Thrm LDO3IntM
*60×0	ILimCntl	R/W**	SysMin[2:0]	SysMin[2:0]	SysMin[2:0]	I	I	I	ILimCntl[1:0]	ונו[1:0]
0x0A*	ChgCntlA	R/W*	I	BatReChg[1:0]	[0:1]gr		BatR	BatReg[3:0]		ChgEn
0x0B*	ChgCntlB	RW*	I		VPChg[2:0]		IPCh	PChg[1:0]	ChgDone[1:0]	ne[1:0]
0×0C*	ChTmr	R/W**	ChgAutoStp	ChgAutoReSta	MtChg	MtChgTmr[1:0]	FChgT	FChgTmr[1:0]	PChgTmr[1:0]	nr[1:0]
0×0	Buck1Cfg	R/W		Buck1Seq[2:0]		Buck1	Buck1En[1:0]	Rese	Reserved	Reserved
0×0E	Buck1VSet	R/W**	Buck1LowEMI	I			Buck	Buck1VSet[5:0]		
0x0F	Buck2Cfg	R/W		Buck2Seq[2:0]		Buck2	Buck2En[1:0]	Rese	Reserved	Reserved
0x10	Buck2VSet	R/W**	Buck2LowEMI	I			Buck	Buck2VSet[5:0]		
0x11	Buck1/2ISet	R/W		Buck2ISet[3:0]	et[3:0]			Buck1	Buck11Set[3:0]	
0x12	LDO1Cfg	R/W		LDO1Seq[2:0]		I	LDO1 ActDSC	LD011	LDO1En[1:0]	LDO1Mode

I2C Register Map (continued)

REGISTER ADDRESS	REGISTER NAME	R/W	B7	B6	B5	B4	B3	B2	B1	B0
0x13	LDO1VSet	R/W**	I	I				LDO1VSet[4:0]		
0x14	LD02Cfg	R/W		LDO2Seq[2:0]		I	LD02 ActDSC	LD02	LDO2En[1:0]	LDO2Mode
0x15	LD02VSet	R/W*	I	I	I			LDO2VSet[4:0]		
0x16	LD03Cfg	R/W		LDO3Seq[2:0]		I	LDO3 ActDSC	LD03	LDO3En[1:0]	LDO3Mode
0x17	LD03VSet	R/W**	1	I	I			LDO3VSet[4:0]		
0x18*	ThrmCfg	R/W		T1T2lFchg[2:0]			T2T3IFchg[2:0]		ThermEn[1:0]	in[1:0]
0x19*	ThrmCfg	R/W	ı	ı	1	I	ı		T3T4IFchg[2:0]	
0x1A	MONCfg	R/W			MONRat	MONRatioCfg[1:0]	MONHIZ		MONCtr[2:0]	
0x1B	BootCfg	R/W		PwrRstCfg[3:0]	g[3:0]		SftRstCfg	Boot	BootDly[1:0]	ChgAlwTry
0x1C	PinStat	R/W		Lim_T[2:0]		I	PFN1	PFN2	MPC1	MPC0
0x1D	Buck1/2Extra	R/W	Buck2lAdptEnb	Buck2Fst	Buck2 ActDsc	Buck2FFET	Buck1IAdptEnb	Buck1Fst	Buck1ActDSC	Buck1FFET
0x1E	PwrCfg	R/W	PFNxResEna	I		I		I	1	StayOn
0x1F	PwrCmd	R/W				JQ	PWR_CMD			

Note: COR = Clear-on-read

*Register is reset to default value upon CHGIN rising edge.

** R if WriteProtect enabled (Table 38).

All R/W registers are reset to default value when entering the off state.

Reserved bits must not be modified from their default states to ensure proper operation.

I²C Register Descriptions

Table 4. Chipld Register (0x00)

ADDRESS:	0x00							
MODE:	Read-Only							
BIT	7	6	5	4	3	2	1	0
NAME				Chip_	ld[7:0]			
Chip_ld[7:0]	Chip_Id[7:0] I	bits show infor	mation about t	he version of t	he MAX14745	i.		

Table 5. ChipRev Register (0x01)

ADDRESS:	0x01							
MODE:	Read-Only							
BIT	7	6	5	4	3	2	1	0
NAME				Chip_F	Rev[7:0]			
Chip_Rev[7:0]	Chip_Rev[7:0] bits show inf	formation abou	t the revision o	of the MAX147	745 silicon.		

Table 6. StatusA Register (0x02)

ADDRESS:	0x02							
MODE:	Read-Only							
BIT	7	6	5	4	3	2	1	0
NAME	_	_		ThermStat[2:0	0]		ChgStat[2:0]	
ThermStat[2:0]	000 = T < T1 001 = T1 < T 010 = T2 < T 011 = T3 < T 100 = T > T4 101 = No the thermistor mand the state of the state	< T3 < T4	ed (THM high node may not nrough Therm	function prope En[1:0]	,	e that if a paralle	el resistor is us	ed for
ChgStat[2:0]	010 = Pre-ch 011, 100 = Fa 101 = Mainta 110 = Mainta	er off	ss progress rogress er done	· · ·	gure 5a and Fig e 5b)	gure 5b)		

Table 7. StatusB Register (0x03)

ADDRESS:	0x03							
MODE:	Read-Only							
BIT	7	6	5	4	3	2	1	0
NAME	UVLOLDO2	UVLOLDO3	ILim	UsbOVP	UsbOk	Chg ThrmSd	Chg ThrmReg	ChgTmo
UVLOLDO2		D2 UVLO normal operatinຸ age-lockout on						
UVLOLDO3		D2 UVLO normal operatinຸ age-lockout on	,					
ILim		Current Limit put current is w put is in current						
UsbOVP	Status of CHO 0 = CHGIN O 1 = CHGIN O	VP is not active						
UsbOk	Status of CHGIN Input 0 = CHGIN Input is not present or outside of valid range. 1 = CHGIN Input is present and valid.							
ChgThrmSd	Status of Thermal Shutdown 0 = Charger and input current limiter is in normal operating mode. 1 = Charger and input current limiter is in thermal shutdown.							
ChgThrmReg	0 = Charger is	rmal Regulation s functioning no s running in the eating.	rmally, or disa		arging curren	t is being activ	ely reduced to	prevent
ChgTmo	0 = Charger is	e-Out Condition s running norma nas reached a ti	ally, or disable		1 11 in this co	ndition (see Fi	gure 5).	

Table 8. StatusC Register (0x04)

ADDRESS:	0x04							
MODE:	Read-Only							
BIT	7	6	5	4	3	2	1	0
NAME	_	SysBLim	VLim	ThrmBuck1	ThrmBuck2	ThrmLDO1	ThrmLDO2	ThrmLDO3
SysBLim	from SYS to oreduces charge one of the foll 0 = Charge C	charge the bat ge current to p lowing two cor urrent is norm	tery. If the tota prevent VSYS nditions is true al.	nit. While the sy al load exceeds from collapsing :: 1. VSYS - VE aced to prevent	the input curre g. The regulation AT = 100mV (t	ent limit, an ada on of the charg yp) OR 2. V _{SY}	aptive charger e current starts	control loop when either
VLim	maintain a 40 case that a po 0 = CHGIN in	mV drop betw ower adapter v put current lin	veen CHGIN-S with insufficier nit is functionin	s bit indicates if SYS. This adap nt load capabilit ng normally. iively reduced t	otive input curre sy, or a high res	ent limit preven	its adapter colla ng cable is use	apse in the d.
ThrmBuck1	0 = Buck1 NOT in Thermal Off mode 1 = Buck1 in Thermal Off Mode							
ThrmBuck2	0 = Buck2 NC 1 = Buck2 in							
ThrmLDO1	0 = LDO1 NC 1 = LDO1 in T							
ThrmLDO2	0 = LDO2 NC 1 = LDO2 in 7							
ThrmLDO3	0 = LDO3 NC 1 = LDO3 in 7	T in Thermal Thermal Off M						

Table 9. IntA Register (0x05)

ADDRESS:	0x05							
MODE:	Clear On Re	ad						
BIT	7	6	5	4	3	2	1	0
NAME	Therm StatInt	ChgStatInt	lLimInt	UsbOVPInt	UsbOk	Chg ThrmSdInt	Therm RegInt	Chg TmoInt
ThermStatInt	Change in Th	nermStat cause	ed interrupt.					
ChgStatInt	Change in Cl	ngStat caused	interrupt, or fir	st detection co	mplete after P	OR.		
lLimInt	Input current	limit triggered	caused interru	ıpt.				
UsbOVPInt	Change in UsbOVP caused interrupt.							
UsbOk	Change in Us	sbOk caused ir	nterrupt.					
ChgThrmSdInt	Change in Cl	ngThrmSd cau	sed interrupt.					
ThermRegInt	Change in Cl	ngThrmReg ca	used interrupt	-				
ChgTmoInt	Change in Cl	ngTmo caused	interrupt.					

Table 10. IntB Register (0x06)

ADDRESS:	0x06							
MODE:	Clear On Re	ad						
BIT	7	6	5	4	3	2	1	0
NAME	_	SysBLimInt	VLimInt	Thrm Buck1Int	Thrm Buck2Int	Thrm LDO1Int	Thrm LDO2Int	Thrm LDO3Int
SysBLimInt	Minimum SY	S-BAT voltage	limit caused in	nterrupt				
VLimInt	Input Voltage	Limit caused i	interrupt					
ThrmBuck1Int	Change in Th	nrmBuck1 caus	sed interrupt.					
ThrmBuck2Int	Change in ThrmBuck2 caused interrupt.							
ThrmLDO1Int	Change in Th	nrmLDO1 caus	ed interrupt.					
ThrmLDO2Int	Change in Th	nrmLDO2 caus	ed interrupt.					
ThrmLDO3Int	Change in Th	nrmLDO3 caus	ed interrupt.					

Table 11. IntMaskA Register (0x07)

ADDRESS:	0x07							
MODE:	Read/Write							
BIT	7	6	5	4	3	2	1	0
NAME	Therm StatIntM	Chg StatIntM	ILimIntM	Usb OVPIntM	UsbOkM	ChgThrm SdIntM	Therm RegIntM	Chg TmoIntM
ThermStatIntM	ThermStatInt 0 = Mask 1 = Not mask		ThermStatInt ir	terrupt in the I	ntA register (0:	x05).		
ChgStatIntM	ChgStatIntM 0 = Mask 1 = Not mask		gStatInt interru	ipt in the IntA r	egister (0x05).			
ILimIntM	ILimIntM mas 0 = Mask 1 = Not mask		interrupt in the	e IntB register ((0x06).			
UsbOVPIntM	UsbOVPIntM 0 = Mask 1 = Not mask		bOVPInt inter	rupt in the IntA	register (0x05).		
UsbOkM	UsbOkM masks the UsbOk interrupt in the IntB register (0x06). 0 = Mask 1 = Not masked							
ChgThrm SdIntM	ChgThrmSdI 0 = Mask 1 = Not mask		· ChgThrmSdIr	nt interrupt in th	ne IntB registe	r (0x06).		
ThermRegIntM	ThermRegInt 0 = Mask 1 = Not mask		ΓhermRegInt ir	nterrupt in the I	ntA register (0	x05).		
ChgTmoIntM	ChgTmoIntM 0 = Mask 1 = Not mask		gTmoInt interr	upt in the IntA	register (0x05)).		

Table 12. IntMaskB Register (0x08)

ADDRESS:	0x08							
MODE:	Read/Writ	te						
BIT	7	6	5	4	3	2	1	0
NAME	_	SysB LimIntM	VLimIntM	Thrm Buck1IntM	Thrm Buck2IntM	Thrm LDO1IntM	Thrm LDO2IntM	Thrm LDO3IntM
SysBLimIntM	SysBLimIr 0 = Mask 1 = Not ma		he SysBLimInt	interrupt in the I	ntB register (0x	:06).		
VLimIntM	VLimIntM 0 = Mask 1 = Not ma		/LimInt interrup	t in the IntB reg	ister (0x06).			
ThrmBuck1 IntM	0 = Mask 1 = Not ma	asked						
ThrmBuck2 IntM	0 = Mask 1 = Not masked							
ThrmLDO1 IntM	0 = Mask 1 = Not ma	asked						
ThrmLDO2 IntM	0 = Mask 1 = Not ma	asked						
ThrmLDO3 IntM	0 = Mask 1 = Not ma	asked						

Table 13. ILimCntl Register (0x09)

ADDRESS:	0x09							
MODE:	Read/Write*	or Read-Only	if Write-Prote	ect Enabled (s	see Table 38)			
BIT	7	6	5	4	3	2	1	0
NAME	SysMin[2:0] — — — ILimCntl [1:							Intl [1:0]
SysMin[2:0]	SysMin sets System Voltage Minimum Threshold. When SYS drops to this level, the charger current is reduced. 000 = 3.6V 001 = 3.7V 010 = 3.8V 011 = 3.9V 100 = 4.0V 101 = 4.1V 110 = 4.2V 111 = 4.3V							
ILimCntl[1:0]				etails)				

^{*}Register is reset to default value upon CHGIN rising edge.

Table 14. ChgCntlA Register (0x0A)

ADDRESS:	0x0A								
MODE:	Read/Write*	or Ready-On	ly if Write-Pro	tect Enabled	(see Table 38))			
BIT	7	6	5	4	3	2	1	0	
NAME		BatReChg[1:0] BatReg[3:0] Chgl							
BatReChg[1:0]	00 = BatReg 01 = BatReg 10 = BatReg	Recharge Threshold in Relation to BatReg 00 = BatReg - 70mV 01 = BatReg - 120mV 10 = BatReg - 170mV 11 = BatReg - 220mV							
BatReg[3:0]	0000 = 4.05\ 0001 = 4.10\ 0010 = 4.15\ 0011 = 4.20\ 0100 = 4.25\ 0101 = 4.35\ 0110 = 4.35\ 0111 = 4.4\ 1000 = 4.45\ 1001 = 4.5\	1000 = 4.45V 1001 = 4.5V 1010 = 4.55V							
ChgEn	On/Off Control for Charger (does not affect SYS node). 0 = Charger disabled. 1 = Charger enabled.								

^{*}Register is reset to default value upon CHGIN rising edge.

Table 15. ChgCntlB Register (0x0B)

ADDRESS:	0x0B							
MODE:	Read/Write*	or Ready-O	nly if Write-Prot	ect Enabled	(see Table 38)			
BIT	7	6	5	4	3	2	1	0
NAME	-	VPChg[2:0]			IPCh	g[1:0]	ChgDo	ne[1:0]
VPChg[2:0]	Pre-charge vo 000 = 2.10V 001 = 2.25V 010 = 2.40V 111 = 2.55V 100 = 2.70V 101 = 2.85V 110 = 3.00V 111 = 3.15V	oltage thresh	old setting					
IPChg[1:0]	Pre-charge cu 00 = 0.05 x I _F 01 = 0.1 x I _F C 10 = 0.2 x I _F C 11 = 0.3 x I _F C	Chg :HG						
ChgDone[1:0]	Charge Done 00 = 0.05 x I _F 01 = 0.1 x I _{FC} 10 = 0.2 x I _{FC} 11 = 0.3 x I _{FC}	Threshold S Chg chg	etting					

^{*}Register is reset to default value upon CHGIN rising edge.

Table 16. ChTmr Register (0x0C)

ADDRESS:	0x0C	0x0C									
MODE:	Read/Write* o	r Ready-Only if W	rite-Prote	ct Enabled	(see Table 38))					
BIT	7	6	5	4	3	2	1	0			
NAME	ChgAutoStp	ChgAutoStp ChpAutoReSta MtChgTmr[1:0] FChgTmr[1:0] PChgTmr[1:0]									
ChgAutoStp	0 = Auto-stop	Charger Auto-Stop. Controls the transition from Maintain Charger to Maintain Charger Done. 0 = Auto-stop disabled. 1 = Auto-stop enabled.									
ChgAutoReSta	0 = Charger re Charger state	harger Auto-Restart Control - Charger remains in maintain charge done even when VBAT is less than charge restart threshold (see harger state diagram) - Charger automatically restarts when VBAT drops below charge restart threshold									
MtChgTmr [1:0]	Maintain Charg 00 = 0min 01 = 15min 10 = 30min 11 = 60min	Maintain Charge Timer Setting 00 = 0min 01 = 15min 10 = 30min									
FChgTmr[1:0]	Fast-Charge T 00 = 75min 01 = 150min 10 = 300min 11 = 600min	imer Setting									
PChgTmr[1:0]	Precharge Tim 00 = 30min 01 = 60min 10 = 120min 11 = 240min	er Setting									

^{*}Register is reset to default value upon CHGIN rising edge.

Table 17. Buck1Cfg Register (0x0D)

ADDRESS:	0x0D											
MODE:	Read/Write	Read/Write										
BIT	7	6	5	4	3	2	1	0				
NAME	Buck1Seq[2:0] (Read-only) Buck1En[1:0] Reserved Reserved							erved				
Buck1Seq[2:0]	000 = Disable 001 = Reserve 010 = Enable 011 = Enable 100 = Enable 101 = Reserve 110 = Reserve	ed ved ed at 0% of Bo ed at 25% of Bo ed at 50% of Boved ved	ot/POR Procesoot/POR Procesoot/POR Procesoot/POR Procesoot/POR after 10	ess Delay Cor ess Delay Cor	ntrol ntrol	s Delay Control						
Buck1En[1:0]	Buck1 Enable Configuration (effective only when Buck1Seq = 111) 00 = Disabled (Buck1 OUT not actively discharged unless in Hard Reset/ShutDown/Off Mode) 01 = Enabled 10 = Enabled when MPC0 is high (regardless of MPC1) 11 = Enabled when MPC1 is high (regardless of MPC0)											

Table 18. Buck1VSet Register (0x0E)

ADDRESS:	0x0E	0x0E									
MODE:	Read/Write										
BIT	7	7 6 5 4 3 2 1 0									
NAME	Buck1LowEMI	_			Buck1\	/Set[5:0]					
Buck1LowEMI	0 = Normal rising	/falling slo	Falling Slopes Setting alling slopes on BLX ing/falling slopes on BLX by a factor of three.								
Buck1VSet [5:0]	Buck1 Output Vo Linear Scale from 000000 = 0.8V 000001 = 0.825V 111111 = 2.375V	n 0.8V to 2	•	V increments							

Changes in output voltages are digitally ramped in 25mV increments every 80µs giving a maximum slew rates of 312.5V/s.

Table 19. Buck2Cfg Register (0x0F)

ADDRESS:	0x0F	0x0F									
MODE:	Read/Write or Read-Only if Write-Protect Enabled (See Table 38)										
BIT	7	7 6 5 4 3 2 1 0									
NAME	Buck	2Seq[2:0] (Rea	id-only)	Buck2E	n[1:0]	Reserved	Rese	erved			
Buck2Seq[2:0]	000 = Disal 001 = Rese 010 = Enab 011 = Enab 100 = Enab 101 = Rese 110 = Rese	Buck2 Enable Configuration (Read-only) 000 = Disabled 001 = Reserved 010 = Enabled at 0% of Boot/POR Process Delay Control 011 = Enabled at 25% of Boot/POR Process Delay Control 100 = Enabled at 50% of Boot/POR Process Delay Control 101 = Reserved 110 = Reserved 111 = Controlled by Buck2En [1:0] after 100% of Boot/POR Process Delay Control									
Buck2En[1:0]	Buck2 Enable Configuration (effective only when Buck2Seq = 111) 00 = Disabled (Buck2 OUT not actively discharged unless in Hard Reset/ShutDown/Off Mode) 01 = Enabled 10 = Enabled when MPC0 is high (regardless of MPC1) 11 = Enabled when MPC1 is high (regardless of MPC0)										

Table 20. Buck2VSet Register (0x10)

ADDRESS:	0x10	0x10								
MODE:	Read/Write or Read-Only if WriteProtect Enabled (see Table 38)									
BIT	7	7 6 5 4 3 2 1 0								
NAME	Buck2LowEMI	_			Buck2	2VSet[5:0]				
Buck2LowEMI	0 = Normal rising	Rising/Falling Slopes Setting rising/falling slopes on BLX the rising/falling slopes on BLX by a factor of three.								
Buck2VSet [5:0]	Buck2 Output Vo Linear Scale from 000000 = 0.80V 000001 = 0.85V 111111 = 3.95V	0 0	/ in 50mV i	increments						

Changes in output voltages are digitally ramped in 50mV increments every 40µs giving a maximum slew rates of 1250V/s.

Table 21. Buck1/2ISet Register (0x11)

ADDRESS:	0x11											
MODE:	Read/Write	Read/Write										
BIT	7	7 6 5 4 3 2 1 0										
NAME		Buck2lSet[3:0] Buck1lSet[3:0]										
Buck2lSet[3:0]	0000 = Rese 0001 = Rese											
Buck1lSet[3:0]	0000 = Rese 0001 = Rese 0010 = 50m	Buck1 Inductor Peak Current Setting. 25mA step 0000 = Reserved 0001 = Reserved 0010 = 50mA										

Table 22. LDO1Cfg Register (0x12)

ADDRESS:	0x12								
MODE:	Read/Write								
BIT	7	6	5	4	3	2	1	0	
NAME	LDO1Seq[2:0] (Read Only) — LDO1Act DSC LDO1En[1:0] LD							LDO1Mode	
LDO1Seq[2:0]	000 = Disable 001 = Enable 010 = Enable 011 = Enable 100 = Enable 101 = Disable 110 = Disable	DO1 Enable Configuration (Read-only) 000 = Disabled 001 = Enabled always when BAT/SYS is present 010 = Enabled at 0% of Boot/POR Process Delay Control 011 = Enabled at 25% of Boot/POR Process Delay Control 100 = Enabled at 50% of Boot/POR Process Delay Control 101 = Disabled 101 = Disabled 111 = Controlled by LDO1En[1:0] after 100% of Boot/POR Process Delay Control							
LDO1ActDSC	0: LDO1 outp 1: LDO1 outp discharge cir	out will be activ	vely discharged vely discharged ue to draw add		Reset mode mode and also ent current as lo		-		
LDO1En[1:0]	LDO1 Enable Configuration (effective only when LDO1Seq = 111) 00 = Disabled 01 = Enabled 10 = Enabled when MPC0 is high (regardless of MPC1) 11 = Enabled when MPC1 is high (regardless of MPC0)								
LDO1Mode	LDO1 Mode Control 0 = Normal LDO operating mode 1 = Load switch mode. FET is either fully ON or OFF depending on state of LDO1En. When FET is ON, the output is unregulated. This setting is internally latched and can change only when the LDO is disabled.								

Table 23. LDO1VSet Register (0x13)

ADDRESS:	0x13									
MODE:	Read/Write or Read-Only if WriteProtect Enabled (see Table 38)									
BIT	7	6	5	4	3	2	1	0		
NAME	-	-	-			LDO1Vset[4:0]]			
LDO1VSet[4:0]		<i>'</i>	_	increments						

Table 24. LDO2Cfg Register (0x14)

ADDRESS:	0x14										
MODE:	Read/Write	or Read-Only	if Write-Prote	ct Enabled (S	ee Table 38)						
BIT	7	6	5	4	3	2	1	0			
NAME	LDO2Seq[2:0] (Read Only) — LDO2Act DSC LDO2En[1:0]						En[1:0]	LDO2 Mode			
LDO2Seq[2:0]	000 = Disabl 001 = Enable 010 = Enable 011 = Enable 100 = Enable 101 = Disabl 110 = Disable	DO2 Enable Configuration (Read only) 00 = Disabled 01 = Enabled always when BAT/SYS is present 10 = Enabled at 0% of Boot/POR Process Delay Control 11 = Enabled at 25% of Boot/POR Process Delay Control 00 = Enabled at 50% of Boot/POR Process Delay Control 01 = Disabled 10 = Disabled 11 = Controlled by LDO2En[1:0] after 100% of Boot/POR Process Delay Control									
LDO2ActDSC	0 = LDO2 ou 1 = LDO2 ou discharge cir	tput will be ac	tively discharge tively discharge	ed in HardRese ditional quiesce	IReset mode et mode and als ent current as lo						
LDO2En[1:0]	00 = Disable 01 = Enabled 10 = Enabled	LDO2 Enable Configuration (effective only when LDO2Seq = 111) 00 = Disabled – LDO's OUT not actively discharged unless HardReset/ShutDown/Off Mode 01 = Enabled 10 = Enabled when MPC0 is high (regardless of MPC1) 11 = Enabled when MPC1 is high (regardless of MPC0)									
LDO2Mode	LDO2 Mode Control 0 = Normal LDO operating mode 1 = Load switch mode. FET is either fully ON or OFF depending on state of LDO2En. When FET is ON, the output is unregulated. This setting is internally latched and can change only when the LDO is disabled.										

Table 25. LDO2VSet Register (0x15)

ADDRESS:	0x15	0x15										
MODE:	Read/Write	Read/Write or Read-Only if WriteProtect Enabled (see Table 38)										
BIT	7	7 6 5 4 3 2 1 0										
NAME	_	LDO2Vset[4:0]										
LDO2VSet[4:0]		/	•	increments								

Table 26. LDO3Cfg Register (0x16)

ADDRESS:	0x16							
MODE:	Read/Write							
BIT	7	6	5	4	3	2	1	0
NAME	LDO3	Seq[2:0] (Rea	d-Only)	_	LDO3Act DSC	I DO3En[1:0]		LDO3 Mode
LDO3Seq[2:0]	000 = Disable 001 = Enable 010 = Enable 011 = Enable 100 = Enable 101 = Disable 110 = Disable	ed always whe ed at 0% of Bo ed at 25% of B ed at 50% of B ed	en BAT/SYS is not/POR Proces not/POR Proces not/POR Proces	ss Delay Contr ess Delay Con ess Delay Con	trol	ay Control		
LDO3ActDSC	0 = LDO3 ou 1 = LDO3 ou discharge cir	tput will be ac	tively discharge tively discharge ue to draw add		IReset mode et modes and a ent current as lo		•	
LDO3En[1:0]	00 = Disable 01 = Enable 10 = Enable	LDO is disabled. (See EC table.) LDO3 Enable Configuration (effective only when LDO3Seq == 111) 00 = Disabled. LDO's OUT not actively discharged unless in HardReset/ShutDown/Off Mode 01 = Enabled 10 = Enabled when MPC0 is high (regardless of MPC1) 11 = Enabled when MPC1 is high (regardless of MPC0)						
LDO3Mode	11 = Enabled when MPC1 is high (regardless of MPC0) LDO3 Mode Control 0 = Normal LDO operating mode 1 = Load switch mode. FET is either fully ON or OFF depending on state of LDO3En. When FET is ON, the output is unregulated. This setting is internally latched and can change only when the LDO is disabled.							

Table 27. LDO3VSet Register (0x17)

ADDRESS:	0x17	0x17									
MODE:	Read/Write or Read-Only if WriteProtect Enabled (see Table 38)										
BIT	7	7 6 5 4 3 2 1 0									
NAME	_	_	— LDO3Vset[4:0]								
LDO3VSet[4:0]		/	ng .0V in 100mV	increments							

Table 28. ThrmCfg Register (0x18)

ADDRESS:	0x18							
MODE:	Read/Write	e* or Read-Or	nly if WritePro	tect Enabled	(see Table 38)			
BIT	7	6	5	4	3	2	1	0
NAME		T1T2IFchg[2:	0]		T2T3IFchg[2:0]]	Therm	En[1:0]
T1T2lFchg[2:0]	Fast Charg 000 = 0.2 x 001 = 0.3 x 010 = 0.4 x 011 = 0.5 x 100 = 0.6 x 101 = 0.7 x 110 = 0.8 x 111 = 1 x I _F	CIFChg CIFChg CIFChg CIFChg CIFChg CIFChg CIFChg	Г1-Т2 Tempera	iture Zone				
T2T3lFchg[2:0]	Fast Charg 000 = 0.2 x 001 = 0.3 x 010 = 0.4 x 011 = 0.5 x 100 = 0.6 x 101 = 0.7 x 110 = 0.8 x 111 = 1 x I _F	CIFChg CIFChg CIFChg CIFChg CIFChg CIFChg CIFChg	Г2-Т3 Tempera	iture Zone				
ThermEn[1:0]	00 = Therm 01 = Charg 10 = Charg	jing enabled b	ng Disabled etween T1 and etween T1 and	T4	reduced below T	2 and above T	- 3	

^{*}Register is reset to default value upon CHGIN rising edge.

Table 29. ThrmCfg Register (0x19)

ADDRESS:	0x19										
MODE:	Read/Writ	Read/Write* or Read-Only if WriteProtect Enabled (see Table 38)									
BIT	7 6 5 4 3 2 1 0										
NAME	_	_	_	_	_	T3T4IFchg[2:0]					
T3T4lFchg[2:0]	Fast Charg 000 = 0.2 × 001 = 0.3 × 010 = 0.4 × 011 = 0.5 × 100 = 0.6 × 101 = 0.8 × 111 = 1 x I _I	CIFChg CIFChg CIFChg CIFChg CIFChg CIFChg	3-T4 Tempera	ture Zone							

^{*}Register is reset to default value upon CHGIN rising edge.

Table 30. MONCfg Register (0x1A)

ADDRESS:	0x1A							
MODE:	Read/Write							
BIT	7	6	5	4	3	2	1	0
NAME	_	_	MONRa	tioCfg[1:0]	MONHiZ	MONCtr[2:0]		
MONRatioCfg	MON Resistiv 00 = 4:1 01 = 3:1 10 = 2:1 11 = 1:1	ve Partition Se	lector					
MONHiZ	MON OFF MODE condition 0 = Pulled LOW by 100k pull-down resistor 1 = Hi-Z							
MONCtr[2:0]	000 = MON is 001 = MON c 010 = MON c 011 = MON c 100 = MON c 101 = MON c 111 = MON c	urce selection s not connected connected to a	d to any inter resistive part resistive part resistive part resistive part resistive part resistive part	nal node and i ition of BATT ition of SYS ition of BUCK1 ition of BUCK2 ition of LDO1 ition of LDO2 (ts state depends OUT OUT OUT OUT	on MONHiZ		

Table 31. BootCfg Register (0x1B)

ADDRESS:	0x1B	0x1B									
MODE:	Read-Only	Read-Only									
BIT	7	6	5	4	3	2	1	0			
NAME		PwrRst	Cfg[3:0]		SftRstCfg	BootD	ChgAlwTry				
PwrRstCfg [3:0]	See Table 1										
SftRstCfg	0 = Registers	egister Default do not reset t reset to defau	o default valu	es on soft rese oft reset	t						
BootDly[1:0]	Reset Delay 00 = 80ms 01 = 120ms 10 = 220ms 11 = 420ms	Control (see F	igure 2a, 2b)								
ChgAlwTry	0 = Part latch	condition occ	_	ot process: ed and replace	ed						

Table 32. PinStat Register (0x1C)

ADDRESS:	0x1C									
MODE:	Read Only									
BIT	7	6	5	4	3	2	1	0		
NAME		ILim_T[2:0]		-	PFN1	PFN2	MPC1	MPC0		
ILim_T[2:0]	Monitor of Th 000 = Input L 001 = 100mA 010 = 500mA 100 =1A	imiter Off	Current Setting							
PFN1	PFN1 Input State 0 = pin low 1 = pin high									
PFN2	PFN2 In/Out 0 = pin low 1 = pin high	State								
MPC1	MPC1 Input State 0 = pin low 1 = pin high									
MPC0	MPC0 Input State 0 = pin low 1 = pin high									

Table 33. Buck1/2Extra Control Register (0x1D)

ADDRESS:	0x1D							
MODE:	Read/Write							
BIT	7	6	5	4	3	2	1	0
NAME	Buck2IAdptEnb	Buck2Fst	Buck2 ActDSC	Buck2 FFET	Buck1IAdptEnb	Buck1Fst	Buck1 ActDSC	Buck1 FFET
Buck2lAdptEnb	Buck 2 Peak Current 0 = Enable adaptive peak current 1 = Peak current set by Buck2ISet[3:0]							
Buck2Fst	Buck2 Fast Start 0 = Normal startup 1 = Double the sta		o reduce the	startup time by	half			
Buck2ActDSC	Buck2 Active Discharge Control 0 = Buck2 output will be actively discharged only in HardReset mode 1 = Buck2 output will be actively discharged in HardReset mode and also when its Enable goes Low. Note, when BuckActDSC=1, the active discharge circuit will remain active and draw additional quiescent current even wh Buck2 is disabled.							
Buck2FFET	Buck2 Force FET 0 = FET Scaling d 1 = FET Scaling e	isabled	ces active F	ET size by 50 ^o	% and increases	efficiency fo	or loads <100m	A.)
Buck1lAdptEnb	Buck 1 Peak Curre 0 = Enable adaptiv 1 = Peak current s	e peak curre						
Buck1Fst	Buck1 Fast Start 0 = Normal startup 1 = Double the sta		o reduce the	startup time by	half			
Buck1ActDSC	1 = Double the startup current to reduce the startup time by half Buck1 Active Discharge Control 0 = Buck1 output will be actively discharged only in HardReset mode 1 = Buck1 output will be actively discharged in HardReset mode and also when its Enable goes Low. Note, when BuckActDSC=1, the active discharge circuit will remain active and draw additional quiescent current even when Buck2 is disabled.							
Buck1FFET	Buck1 Force FET 0 = FET Scaling o 1 = FET Scaling e	nly enabled d	uring the Bud	k1 Turn-On Se	equence			A.)

Table 34. PwrCfg Register (0x1E)

ADDRESS:	0x1E	0x1E									
MODE:	Read/Write										
BIT	7	7 6 5 4 3 2 1 0									
NAME	PFNx ResEna	_	-	_	_	_	_	StayOn			
PFNxResEna	PFN_ PFNx Automatic Internal Pull-Up/Pull-Down Enable 0 = No internal pullup/pulldown 1 = Automatic internal pullup/pulldown as per Table 1										
StayOn	prevent the p set.		ng down and r		rectly. This bit repower-off cond						

Table 35. PwrCmd Register (0x1F)

ADDRESS:	0x1F	0x1F									
MODE:	Read/Write										
BIT	7	7 6 5 4 3 2 1 0									
NAME		PWR_CMD[7:0]									
PWR_CMD [7:0]	Writing the for 0xB2 = place 0xC3 = issue 0xD4 = issue After the writ	es the part in or es a hard reset es a soft reset ten value has	ff mode (power cycle) reset pulse or peen validated	nly) I by the interna	ıl logic, this re	gister is clearec each PwrRstCf	,	v. Any other			

Applications Information

The buck converters of the MAX14745 are optimized for use with a tiny inductor and small ceramic capacitors. The correct selection of external components ensures high efficiency, low output ripple, and fast transient response.

Inductor Selection

A 2.2µH inductor is recommended for use with the MAX14745 buck converters. <u>Table 36</u> lists recommended inductors for use depending on whether a given application requires highest efficiency, or a compromise between high efficiency and small size.

Output Capacitor Selection

The output capacitors of the MAX14745 buck converters are required to keep the output voltage ripple small and to ensure regulation loop stability. A $10\mu\text{F}$ output capacitor with Buck_ISet[3:0] = 150mA and Buck_IAdptEnb = 0 is suggested to cover all the possible output voltage/load current cases. If a lower output cap are needed, please refer to Table 37 for the minimum allowed capacitor size). Ceramic capacitors are recommended due to their small size and low ESR and care should be taken to ensure that the selected capacitor maintains its capacitance over temperature and voltage bias. Capacitors with X5R or X7R temperature characteristics perform well in most applications.

Input Capacitor Selection

The input capacitors of the buck converters reduce the current peaks drawn from the battery or input power source and reduces switching noise in the IC. The impedance of the input capacitors at the switching frequency should be kept very low. Ceramic capacitors are recommended due to their small size and low ESR. Make sure the capacitor maintains its capacitance over temperature and DC bias. Capacitors with X5R or X7R temperature characteristics perform well in most applications.

PCB Layout and Routing

High switching frequencies and large peak currents make PCB layout a very important part of design. Good design minimizes excessive EMI on the feedback paths and voltage gradients in the ground plane, both of which can result in instability or regulation errors. Connect the inductor, input capacitor, and output capacitor as close together as possible, and keep their traces short, direct, and wide. Connect the two GND pins under the IC and directly to the grounds of the input and output capacitors. Keep noisy traces, such as the LX node, as short as possible.

Table 36. Suggested Inductors

MANUFACTURER	SERIES	INDUCTANCE (µH)	DC RESISTANCE (mΩ)	CURRENT RATING (mA)	DIMENSIONS L x W x H (mm)	NOTES
BOURNS	SRP2010	2.2	168	2200	2.0 x 1.6 x 1.0	Optimized for highest efficiency
MURATA	MFD160810	2.2	310	1400	1.6 x 0.8 x 1.0	Optimized for smallest size

Table 37. Output Capacitor Values*

BUCK_ISET[3:0]	OUTPUT VOLTAGE (V)	OUTPUT CAPACITOR MINIMUM VALUES (µF)
<150mA	>1.4V	2.2
<200mA	>1.2V	4.7
<175mA	>0.8	10

*Minimum Output Capacitor Values are given for L = 2.2µH

Table 38. Register Bit Default Values

1580 1281	REGISTER	MAX14745A	MAX14745C	MAX14745D	П	MAX14745F	MAX14745G MAX14745H	MAX14745H	MAX 147451	MAX14745.1	MAX14745K	MAX147451	MAX14745M	MAX147450	MAX14745P	MAX147450	MAX14745R	MAX14745S
20m4 20m4 <th< th=""><th>BITS</th><th></th><th></th><th></th><th>; </th><th></th><th></th><th></th><th></th><th></th><th></th><th></th><th></th><th></th><th></th><th></th><th></th><th></th></th<>	BITS				;													
17.2 18.9 <th< th=""><th>Buck1IZC Set[1:0]</th><th>20mA</th><th>30mA</th><th>20mA</th><th>20mA</th><th>20mA</th><th>30mA</th><th>10mA</th><th>30mA</th><th>20mA</th><th>20mA</th><th>20mA</th><th>20mA</th><th>30mA</th><th>10mA</th><th>20mA</th><th>30mA</th><th>30mA</th></th<>	Buck1IZC Set[1:0]	20mA	30mA	20mA	20mA	20mA	30mA	10mA	30mA	20mA	20mA	20mA	20mA	30mA	10mA	20mA	30mA	30mA
15math 15math<	Buck1VSet [5:0]	1.2V	1.95V	1.8V	1.2V	1.2V	1.8V	0.95V	2.375V	1.2V	1.25V	1.125V	1.1V	1.95V	0.95V	1.1V	1.95V	1.8V
Beachtie Despited	Buck1lSet [3:0]	125mA	150mA	125mA	150mA	125mA	125mA	150mA	150mA	150mA	150mA	150mA	150mA	175mA	150mA	150mA	225mA	125mA
Bunklier 9% Boad Bunklier	Buck1En [1:0]	Disabled	Disabled	Disabled	Enabled	Disabled	Disabled	Disabled	Enabled	Disabled	Disabled	Enabled	Enabled	Enabled	Disabled	Enabled	Enabled	Disabled
20m4 40m4 30m4 30m4 20m4 30m4 30m4 40m4 40m4 <th< th=""><th>Buck1Seq [2:0]</th><th>Buck1En</th><th>0% Boot</th><th>Buck1En</th><th>25% Boot</th><th>Buck1En</th><th>0% Boot</th><th>Buck1En</th><th>Buck1En</th><th>Buck1En</th><th>Buck1En</th><th>Buck1En</th><th>50% Boot</th><th>0% Boot</th><th>Buck1En</th><th>50% Boot</th><th>0% Boot</th><th>0% Boot</th></th<>	Buck1Seq [2:0]	Buck1En	0% Boot	Buck1En	25% Boot	Buck1En	0% Boot	Buck1En	Buck1En	Buck1En	Buck1En	Buck1En	50% Boot	0% Boot	Buck1En	50% Boot	0% Boot	0% Boot
130 33V 18V 18V 18V 28V 18V 18V <th>Buck2IZC Set[1:0]</th> <th>20mA</th> <th>40mA</th> <th>30mA</th> <th>30mA</th> <th>20mA</th> <th>20mA</th> <th>30mA</th> <th>30mA</th> <th>30mA</th> <th>30mA</th> <th>40mA</th> <th>30mA</th> <th>40mA</th> <th>30mA</th> <th>30mA</th> <th>40mA</th> <th>20mA</th>	Buck2IZC Set[1:0]	20mA	40mA	30mA	30mA	20mA	20mA	30mA	30mA	30mA	30mA	40mA	30mA	40mA	30mA	30mA	40mA	20mA
125m4 150m4 150m4 <th< th=""><th>Buck2VSet [5:0]</th><th></th><th>3.3V</th><th>3V</th><th>1.8V</th><th>1.8V</th><th>1.2V</th><th>2.6V</th><th>2.7V</th><th>2.85V</th><th>1.8V</th><th>3.3V</th><th>1.9V</th><th>3.4V</th><th>2.6V</th><th>1.9V</th><th>3.4V</th><th>1.2V</th></th<>	Buck2VSet [5:0]		3.3V	3V	1.8V	1.8V	1.2V	2.6V	2.7V	2.85V	1.8V	3.3V	1.9V	3.4V	2.6V	1.9V	3.4V	1.2V
Disabled Disabled Enabled	Buck2ISet [3:0]	125mA	150mA	300mA	150mA	125mA	125mA	150mA	150mA	150mA	150mA	150mA	150mA	175mA	150mA	150mA	375mA	125mA
9% Boot 50% Boot 10% Boot 0% Boot 20% Boot 10% Boot <	Buck2En [1:0]	Disabled	Disabled	Disabled	Enabled	Disabled	Disabled	Enabled	Disabled	Enabled	Enabled	Enabled	Enabled	Disabled	Enabled	Enabled	Enabled	Disabled
LDO LDO <td>Buck2Seq [2:0]</td> <td>0% Boot</td> <td>50% Boot</td> <td>50% Boot</td> <td>25% Boot</td> <td>0% Boot</td> <td>0% Boot</td> <td>25% boot</td> <td>Buck2En</td> <td>25% Boot</td> <td>0% Boot</td> <td>Buck2En</td> <td>50% Boot</td> <td>Buck2En</td> <td>25% Boot</td> <td>50% Boot</td> <td>Buck2En</td> <td>0% Boot</td>	Buck2Seq [2:0]	0% Boot	50% Boot	50% Boot	25% Boot	0% Boot	0% Boot	25% boot	Buck2En	25% Boot	0% Boot	Buck2En	50% Boot	Buck2En	25% Boot	50% Boot	Buck2En	0% Boot
31. Wilch 1.8 W 1.8 W 3.4 W 1.8 W 3.4 W 3.4 W 3.4 W 3.5 W 1.8 W	LD01Mode		ГДО	Switch	ГРО	CDO	ПРО	ГРО	switch	ГРО	ГРО	ГВО	PDO	PDO	ГРО	CDO	PDO	CDO
Disabled	LDO1VSet [4:0]	38	1.87	1.8V	1.8V	3V	38	3.1V	0.87	1.8V	1.8V	3/	2.9V	1.8V	3.1V	2.9V	1.8V	3.3V
LDOTE LBOYER LDOTE LDOTE <t< td=""><td>LD01En [1:0]</td><td>Disabled</td><td>Enabled</td><td>Disabled</td><td>Enabled</td><td>Disabled</td><td>Disabled</td><td>Disabled</td><td>Disabled</td><td>Disabled</td><td>Disabled</td><td>Enabled</td><td>MPC1</td><td>Disabled</td><td>Disabled</td><td>Disabled</td><td>Enabled</td><td>Disabled</td></t<>	LD01En [1:0]	Disabled	Enabled	Disabled	Enabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Enabled	MPC1	Disabled	Disabled	Disabled	Enabled	Disabled
Switch LDO Switch LDO Switch LDO LDO <t< td=""><td>LDO1Seq [2:0]</td><td>LD01En</td><td>25% Boot</td><td>LD01En</td><td>Always On</td><td>LD01En</td><td>LD01En</td><td>LD01En</td><td>LD01En</td><td>LDO1En</td><td>LD01En</td><td>LD01En</td><td>LD01En</td><td>LD01En</td><td>LD01En</td><td>LD01En</td><td>LD01En</td><td>LD01En</td></t<>	LDO1Seq [2:0]	LD01En	25% Boot	LD01En	Always On	LD01En	LD01En	LD01En	LD01En	LDO1En	LD01En							
3.5V 1.8V 1.8V 3.5V 1.8V 3.2V 1.2V 1.2V <th< td=""><td>LDO2Mode</td><td></td><td>CDO</td><td>Switch</td><td>CDO</td><td>Switch</td><td>Switch</td><td>CDO</td><td>ПВО</td><td>CDO</td><td>CDO</td><td>CDO</td><td>Switch</td><td>CDO</td><td>ГДО</td><td>Switch</td><td>TDO</td><td>CDO</td></th<>	LDO2Mode		CDO	Switch	CDO	Switch	Switch	CDO	ПВО	CDO	CDO	CDO	Switch	CDO	ГДО	Switch	TDO	CDO
Disabled Enabled Disabled	LDO2VSet [4:0]	3.5V	1.8V	1.8V	2.8V	3.5V	3.5V	1.8V	3.2V	1.2V	3V	3V	1.9V	1.8V	1.8V	1.9V	1.8V	1.8V
LDOZEn 55% Boot LDOZEn LDOZE	LD02En [1:0]	Disabled	Enabled	Disabled	Enabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Enabled	MPC0	Disabled	Disabled	Disabled	Enabled	Disabled
Switch LDO Switch LDO L	LD02Seq [2:0]	LD02En	25% Boot	LDO2En	50% Boot	LDO2En	LDO2En	LDO2En	LDO2En	LDO2En	LD02En	LD02En	LDO2En	LDO2En	LDO2En	LD02En	LD02En	LD02En
3.5V 1.8V 1.8V 3.5V 1.8V 2V 3V 3V 3V 1.9V 1.8V 1.8V <td>LDO3Mode</td> <td></td> <td>ПВО</td> <td>Switch</td> <td>CDO</td> <td>Switch</td> <td>Switch</td> <td>ПВО</td> <td>ПВО</td> <td>CDO</td> <td>CDO</td> <td>CDO</td> <td>Switch</td> <td>CDO</td> <td>ГРО</td> <td>Switch</td> <td>CDO</td> <td>CDO</td>	LDO3Mode		ПВО	Switch	CDO	Switch	Switch	ПВО	ПВО	CDO	CDO	CDO	Switch	CDO	ГРО	Switch	CDO	CDO
Disabled Enabled Disabled	LD03VSet [4:0]	3.5V	1.8V	1.8V	3.3V	3.5V	3.5V	1.8V	2V	30	30	3/	1.9V	1.8V	1.8V	1.9V	1.8V	2.8V
LD03En 25% Boot LD03En	LD03En [1:0]	Disabled	Enabled	Disabled	Enabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Enabled	Disabled	Disabled	Disabled	Disabled	Enabled	Disabled
2.85V 3.00V 2.85V 3.00V 2.85V 3.00V 3.00V <th< td=""><td>LD03Seq [2:0]</td><td>LD03En</td><td>25% Boot</td><td>LDO3En</td><td>LD03En</td><td>LDO3En</td><td>LDO3En</td><td>LD03En</td><td>LD03En</td><td>LD03En</td><td>LD03En</td><td>LD03En</td><td>LD03En</td><td>LD03En</td><td>LD03En</td><td>LD03En</td><td>LD03En</td><td>LD03En</td></th<>	LD03Seq [2:0]	LD03En	25% Boot	LDO3En	LD03En	LDO3En	LDO3En	LD03En										
0.10 x 0.10 x 0.20 x 0.20 x 0.10 x 0.05 x 0.10 x 0.	VPchg[2:0]	2.85V	3.00V	2.85V	3.00V	2.85V	2.85V	3.00V	2.85V									
	IPChg[1:0]	0.10 x IFChg	0.10 x IFChg	0.20 x IFChg	0.20 x IFChg	0.10 x IFChg	0.10 x IFChg	0.10 x IFChg	0.10 x IFChg	0.10 x IFChg	0.20 x IFChg	0.10 x IFChg	0.05 x IFChg	0.10 x IFChg	0.10 x IFChg	0.05 x IFChg	0.10 x IFChg	0.10 x IFChg

Table 38. Register Bit Default Values (continued)

REGISTER BITS	MAX14745A	MAX14745C	MAX14745A MAX14745C MAX14745D MAX1474	2E	MAX14745F	MAX14745F MAX14745G MAX14745H MAX14745I	MAX14745H		MAX14745J	MAX14745K	MAX14745L	MAX14745M	MAX147450	MAX14745J MAX14745K MAX14745L MAX14745M MAX14745O MAX14745P MAX14745Q MAX14745R MAX14745S	MAX14745Q	MAX14745R	MAX14745S
PChgTmr [1:0]	30min	120min	30min	30min	30min	30min	60min	30min	30min	30min	30min	30min	60min	60min	30min	120min	30min
FChgTmr [1:0]	300min	150min	600min	300min	300min	300min	600min	150min	150min	300min	300min	150min	300min	300min	150min	300min	300min
MtChgTmr [1:0]	60min	15min	0min	30min	60min	60min	0min	15min	0min	30min	0min	0min	0min	0min	0min	60min	60min
BatReg [3:0]	4.20V	4.40V	4.35V	4.20V	4.20V	4.20V	4.15V	4.20V	4.20V	4.35V	4.35V	4.20V	4.35V	4.25V	4.35V	4.35V	4.20V
BatReChg [1:0]	-120mV	-220mV	-120mV	-100mV	-120mV	-120mV	-170mV	-120mV	-170mV	-120mV	-220mV	-220mV	-220mV	-220mV	-70mV	-220mV	-120mV
ChgEn	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Disabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
ChgDone	0.05 x	0.10 x	0.05 x	0.20 x	0.05 x	0.05 x	0.1 x IFChg	0.20 x	0.05 x	0.10 x	0.10 x	0.10 x	0.10 x	0.10 x	0.10 x	0.10 x	0.05 x
ChgAutoStp	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
ChgAutoSta	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
FrshBatDis	Done	Charge	Charge	Charge	Done	Done	Charge	Charge	Charge	Charge	Done	Charge	Charge	Charge	Charge	Charge	Done
ThermEn [1:0]	Thermistor	JEITA 1	Thermistor	Thermistor	JEITA 1	JEITA 1	JEITA2	Thermistor	Thermistor	JEITA 1	JEITA 2	JEITA 2	JEITA 1	JEITA 2	JEITA 2	JEITA 1	JEITA 1
T1_T2_ Fcha[2:0]	1.0 ×	0.5 x IFCha	0.5 x	1.0 x	1.0 x IFCha	1.0 x IFCha	1.0 x IFCha	1.0 x	0.2×	0.2 x IFChg	0.4 x IFChg	0.5 x IFChg	0.5 x IFChg	0.2 x IFChg 0.4 x IFChg 0.5 x IFChg 0.5 x IFChg 1.0 x IFChg 0.5 x IFChg 0.5 x IFChg 0.2 x IFChg	0.5 x IFChg	0.5 x IFChg).2 x IFChg
T2_T3_	1.0 ×	1.0 x	1.0 x	1.0 ×	1.0 x	1.0 x	1.0 x	1.0 x	1.0 x	1.0 x IFChg	0.8 x IFChg	0.8 x IFChg 1.0 x IFChg 1.0 x IFChg	1.0 x IFChg	1.0 x IFChg 1.0 x IFChg	1.0 x IFCha	1.0 x IFChg 0.2 x IFChg).2 x IFChg
IFcng[2:0]	IFChg 1.0 x	IFChg 0.5 x	IFChg 0.2×	1.0 ×	1.0 ×	1.0 ×	1.0 ×	1.0 ×	IFChg 0.2 x					2	,	,	
Fchg[2:0]	IFChg	IFChg	IFChg	IFChg	IFChg	IFChg	IFChg	IFChg		0.2 x IFChg	1.0 x IFChg	1.0 x IFChg 1.0 x IFChg	0.5 x IFChg	1.0 × IFChg 1.0 × IFChg	1.0 x IFChg	0.5 x IFChg 1.0 x IFChg	I.0 x IFChg
ChgAlwTry	Retry	Latch Off	Latch Off	Retry	Retry	Retry	Latch Off	Retry	Retry	Retry	Retry	Latch Off	Latch Off	Latch Off	Latch Off	Latch Off	Retry
ILimCntl [1:0]	500mA	500mA	500mA	500mA	500mA	500mA	500mA	500mA	100mA	500mA	500mA	500mA	1000mA	500mA	500mA	1000mA	500mA
PwrRstCfg [3:0]	KIN (0110)	CR Low (0101)	(0000) #O/vO	KIN (0110)	KIN (0110)	KIN (0110)	Custom1 (0111)	Custom2 (1000)	Custom2 (1000)	Custom1 (0111)	KIN (0110)	Rst Rise(0010)	Custom2 (1000)	Custom1 (0111)	Rst Rise (0010)	On/Off (0000)	Custom1 (0111)
PFNxResEna	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled	Enabled
BootDly [1:0]	(120 + 34) ms	(120 + 34) ms	(420 + 34) ms	(420 + 34) ms	(120 + 34) ms	(120 + 34) ms	(120 + 34) ms	(80 + 34)ms	(120 + 34) ms	(80 + 34) ms	(120 + 34) ms	(80 + 34)ms (80 + 34)ms	(80 + 34)ms	(120 + 34) ms	(80 + 34)ms	(120 + 34) ms	(120 + 34) ms
SftRstCfg	Hold	Reset	Reset	Reset	Hold	Hold	Reset	Reset	Reset	Reset	Reset	Reset	Reset	Reset	Reset	Reset	Hold
SysMin[2:0]	3.6V	3.6V	3.6V	3.6V	3.6V	3.6V	3.6V	3.6V	3.87	3.6V	3.6V	3.6V	3.6V	3.6V	3.6V	3.6V	3.6V
Write- Protect	Writable	Writable	Writable	Writable	Writable	Writable	Writable	Writable	Writable	Writable	Writable	Writable	Writable	Writable	Writable	Writable	Writable
StayOn	Stay On	Stay On	Stay On	Stay On	Stay On	Stay On	Stay On	Stay On	Stay On	Stay On	Stay On	Stay On	Stay On	Stay On	Stay On	Stay On	Stay On
T1, T2, T3, T4	0,10,25, 45°C	0, 10, 25, 45°C	0, 10, 45, 60°C	0, 10, 45, 60°C	0,10,25,45 °C	0,10,25,45 °C	0,10,45,60 °C	0,10,45, 60 °C	0,10,45, 60°C	0,10,45, 60°C	0,10,25, 45°C	0,10,45,60 °C	0,10,25,45 °C	0,10,45,60 °C	0,10,45,60 °C	0,10,25,45 °C	0,10,25,45 °C

Table 39. Register Default Values

		ı																
EGISTER	EGISTER REGISTER		MAX14745A MAX14745C MAX14745D	MAX14745D	MAX14745E	MAX14745F	MAX14745E MAX14745F MAX14745G MAX14745H	MAX14745H	MAX147451 MAX14745J MAX14745K MAX14745L MAX14745M MAX14745O MAX14745P MAX14745Q MAX14745R MAX14745S	MAX14745J	MAX14745K	MAX14745L	MAX14745M	MAX147450	MAX14745P	MAX14745Q	MAX14745R	MAX 147 45S
00×0	Chipld	0x02	0×02	0×02	0x02	0x02	0x02	0x02	0x02	0×02	0x02	0x02	0x02	00×0	0×02	0x02	0×02	0x02
0x01	ChipRev	00×0	0×00	00×0	00×0	00×0	00x0	00×0	00×0	00×0	00×0	00×0	00×0	00×0	00×0	00×0	00×0	0x00
0×07	IntMaskA	00×0	00×00	00×0	00×0	00×0	00×0	00×0	00×0	00×0	00×0	00×0	00×0	00×0	00×0	00×0	00×0	00×0
0x08	IntMaskB	00×0	00×0	00×0	00×0	00×0	00×0	00×0	00×0	00×0	00×0	00×0	00×0	00×0	00×0	00×0	00×0	00×0
60×0	ILimCntl	0×02	0×02	0x02	0×02	0x02	0x02	0x02	0×02	0x41	0x02	0x02	0x02	00×0	0x02	0×02	0×03	0x02
0×0A	ChgCntlA	0x27	0x6F	0x2D	0x27	0x27	0x27	0x45	0x27	0×46	0x2D	Ω9×0	0×67	00×0	69×0	□0×0	09X0	0x27
0x0B	ChgCntlB	0x54	0x65	0x58	0x6A	0x54	0x54	0x65	99×0	0x64	69×0	0x65	0x61	00×0	0x65	0x61	0x65	0x54
0×0C	ChTmr	0xF8	9Qx0	0xCC	0xE8	0xF8	0xF8	ОХС	0xD4	0xC4	0xE8	0xC8	0xC4	00×0	0xC9	0xC4	0xFA	0xF8
0×0D	Buck1Cfg	0xE1	0x42	0xE1	69×0	0xE1	0x42	0×E0	0xEA	0xE1	0xE1	0xE9	0x89	00×0	0×E0	0x89	0x4A	0x42
0x0E	Buck1V- Set	0×10	0x2E	0x28	0x10	0x10	0x28	90×0	0x3F	0x10	0x12	0×0D	0×0C	00×0	90×0	0×0C	0x2E	0x28
0x0F	Buck2Cfg	0x41	0x83	0x82	0x6A	0x41	0x41	0x6A	0xE2	0x6A	0x4A	0xEB	0x8A	00×0	0x6A	0x8A	0xEB	0x41
0x10	Buck2V- set	0x14	0x32	0x2C	0x14	0x14	0×08	0x24	0x26	0x29	0x14	0x32	0x16	00×0	0x24	0x16	0x34	0×08
0x11	BucklSet	0x55	99×0	0xC5	99×0	0x55	0x55	99×0	99×0	99×0	99x0	99x0	99x0	00×00	99×0	99×0	0xF9	0x55
0x12	LDO1Cfg	0×E0	0x62	0xE1	0x22	0xE0	0xE0	0×E0	0xE1	0×E0	0×E0	0xE2	0xE6	00×0	0xE0	0×E0	0xE2	0xE0
0x13	LDO1V- Set	0x16	0x0A	0x0A	0×0A	0x16	0x16	0x17	00×0	0x0A	0x0A	0x16	0x15	00×0	0x17	0x15	0x0A	0x19
0x14	LD02Cfg	0xE1	0x62	0xE1	0x82	0xE1	0xE1	0×E0	0×E0	0×E0	0×E0	0xE2	0xE5	00×0	0xE0	0xE1	0xE2	0xE0
0x15	LDO2V- Set	0x1A	60×0	60×0	0x13	0x1A	0x1A	60×0	0x17	0×03	0x15	0x15	0x0A	0000	60×0	0x0A	60×0	60×0
0x16	LDO3Cfg	0xE1	0x62	0xE1	0xE2	0xE1	0xE1	0xE0	0×E0	0×E0	0×E0	0xE2	0xE1	00×0	0xE0	0xE1	0xE2	0xE0
0x17	LDO3V- Set	0x1A	0×09	60×0	0x18	0x1A	0x1A	60×0	0x0B	0x15	0x15	0x15	0x0A	00×0	60×0	0x0A	60×0	0x13
0x18	THRM- CFA	0xFD	0x7E	0x7D	0xFD	0xFE	0xFE	0xFF	0xFD	0x1D	0x1E	0x5B	0x7F	00×0	0xFF	0x7F	0×7E	0x02
0x19	THRM- CFB	0x07	0x03	00×00	0×07	0×07	0×07	0×07	0×07	00×0	0×00	0×07	0x07	00×0	0×07	0×07	0x03	0×07
0x1A	MONCFG	0x00	00×0	00×0	00×0	00x0	00×0	00×0	00×0	00×0	00×0	00x0	00×0	00×0	00×0	00×0	00×0	0x00
0x1B	воотсге	0x63	0x5A	0×0E	0x2F	0x63	0x63	0x7A	0x89	0x8B	0x79	0x6B	0x28	0000	0x7A	0×28	0x0A	0x73
0x1D	Buck1/2 Extra	0×00	0x00	00×00	00×0	0×00	0×00	0×00	0x00	00×0	0×00	0×00	0x00	00×0	0×00	0×00	0×00	00×0
0x1E	PwrCfg	0x81	0x81	0x81	0x81	0x81	0x81	0x81	0x81	0x81	0x81	0x81	0x81	00×0	0x81	0x81	0x81	0x81
0x1F	PwrCmd	0×00	0x00	00×0	0x00	00×0	00x0	00×0	00×0	00×0	00×0	0x00	00×0	00×0	00×0	00×0	00×0	0x00

Ordering Information

TEMP RANGE	PIN-PACKAGE
-40°C to +85°C	36 WLP
	-40°C to +85°C

PART	TEMP RANGE	PIN-PACKAGE
MAX14745KEWX+T	-40°C to +85°C	36 WLP
MAX14745LEWX+	-40°C to +85°C	36 WLP
MAX14745LEWX+T	-40°C to +85°C	36 WLP
MAX14745MEWX+	-40°C to +85°C	36 WLP
MAX14745MEWX+T	-40°C to +85°C	36 WLP
MAX147450EWX+	-40°C to +85°C	36 WLP
MAX14745OEWX+T	-40°C to +85°C	36 WLP
MAX14745PEWX+	-40°C to +85°C	36 WLP
MAX14745PEWX+T	-40°C to +85°C	36 WLP
MAX14745QEWX+	-40°C to +85°C	36 WLP
MAX14745QEWX+T	-40°C to +85°C	36 WLP
MAX14745REWX+	-40°C to +85°C	36 WLP
MAX14745REWX+T	-40°C to +85°C	36 WLP
MAX14745SEWX+	-40°C to +85°C	36 WLP
MAX14745SEWX+T	-40°C to +85°C	36 WLP

⁺Denotes a lead(Pb)-free package/RoHS-compliant package. T = Tape and reel.

Chip Information

PROCESS: BiCMOS

^{*}Future Product—contact factory for availability.

See <u>Table 38</u> and <u>Table 39</u> for the device differences.

Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	6/16	Initial release	_
1	10/16	Added new part numbers and corrected various errors	4–7, 15, 16, 24, 26, 31, 47, 50, 53, 58, 59
2	11/16	Changed future product status of MAX14745C/MAX14745D and various updates	5, 23–25, 36, 46–48, 60
3	3/17	Removed future product asterisks from MAX14745EEWX+ and MAX14745EEWX+T in the <i>Ordering Information</i> table.	61
4	5/17	MAX14745E no longer future product. Updated Table 38 and Table 39	58–61
5	6/17	Removed future product asterisks from MAX14745FEWX+ and MAX14745FEWX+T in the <i>Ordering Information</i> table.	61
6	8/17	Updated Tables 38, 39, and added MAX14745GEWX, MAX14745GEWX+T, MAX14745HEWX, MAX14745HEWX+T to the <i>Ordering Information</i> table	63–66
7	10/17	Removed future product asterisks from MAX14745GEWX+ and MAX14745GEWX+T in the <i>Ordering Information</i> table	66
8	2/18	Added new parts to the <i>Ordering Information</i> table. Updated Tables 23, and 38–39	54, 63–66
9	2/18	Updated Figure 2a, Tables 38–39, and added new future parts to the <i>Ordering Information</i> table.	30, 63–66
10	4/18	Updated Figures 5a and 5b, and removed future part designation from MAX14745IEWX and MAX14745IEWX+T in the <i>Ordering Information</i> table.	36–37, 66
11	5/18	Updated title, Tables 38 and 29, removed future part designation from MAX14745KEWX and MAX14745KEWX+T, and added MAX14745LEWX and MAX14745LEWX+T as future products to the <i>Ordering Information</i> table.	1–67
12	6/18	Updated Table 39 and the Ordering Information table	65–66
13	7/18	Updated Table 38, Table 39, and removed future product designation from MAX14745HEWX+ and MAX14745HEWX+Tthe <i>Ordering Information</i> table	63–66
14	10/18	Updated Table 38, Table 39, and added MAX14745MEWX+, MAX14745MEWX+T and future products MAX14745OEWX+, MAX14745OEWX+T to the <i>Ordering Information</i> table	63–66
15	3/19	Updated the <i>Bump Description</i> and Table 38; removed future product designation from MAX147450EWX+ and MAX147450EWX+T, and added MAX14745PEWX+ and MAX14745PEWX+T as future parts to the <i>Ordering Information</i> table	26, 63–64, 66
16	4/19	Removed future product asterisks from MAX14745PEWX+ and MAX14745PEWX+T in the <i>Ordering Information</i> table	66
17	5/19	Updated Table 38	64
18	7/19	Corrected errors in Table 38	64
19	8/19	Updated Table 38	64
20	2/20	Updated Table 38 and Table 39; added MAX14745QEWX+, MAX14745QEWX+T, MAX14745SEWX+ and MAX14745EWX+T as future products, and MAX14745REWX+ and MAX14745REWX+T to the <i>Ordering Information</i> table	63–65
21	7/20	Removed future product designation from MAX14745SEWX+ and MAX14745SEWX+T in the <i>Ordering Information</i> table	66
22	9/20	Removed future product designation from MAX14745QEWX+ and MAX14745QEWX+T in the <i>Ordering Information</i> table	66

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